

US011769735B2

(12) **United States Patent**
Pietambaram et al.

(10) **Patent No.:** **US 11,769,735 B2**
(45) **Date of Patent:** **Sep. 26, 2023**

(54) **CHIPLET FIRST ARCHITECTURE FOR DIE TILING APPLICATIONS**

(71) Applicant: **Intel Corporation**, Santa Clara, CA (US)

(72) Inventors: **Srinivas Pietambaram**, Chandler, AZ (US); **Gang Duan**, Chandler, AZ (US); **Deepak Kulkarni**, Chandler, AZ (US); **Rahul Manepalli**, Chandler, AZ (US); **Xiaoying Guo**, Chandler, AZ (US)

(73) Assignee: **Intel Corporation**, Santa Clara, CA (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 821 days.

(21) Appl. No.: **16/274,086**

(22) Filed: **Feb. 12, 2019**

(65) **Prior Publication Data**

US 2020/0258847 A1 Aug. 13, 2020

(51) **Int. Cl.**
H01L 21/56 (2006.01)
H01L 23/00 (2006.01)
(Continued)

(52) **U.S. Cl.**
CPC **H01L 23/562** (2013.01); **H01L 21/4853** (2013.01); **H01L 21/4857** (2013.01);
(Continued)

(58) **Field of Classification Search**
CPC H01L 23/562; H01L 21/4853; H01L 21/4857; H01L 21/565; H01L 21/568; H01L 23/3121; H01L 23/5383; H01L 23/5386; H01L 23/5389; H01L 24/19; H01L 24/20; H01L 2224/214;
(Continued)

(56) **References Cited**

U.S. PATENT DOCUMENTS

8,901,748 B2 12/2014 Manusharow
9,190,380 B2* 11/2015 Teh H01L 23/50
(Continued)

FOREIGN PATENT DOCUMENTS

TW 202021073 6/2020
WO WO 2018/009145 1/2018

(Continued)

OTHER PUBLICATIONS

Search Report for European Patent Application No. 20174455.4, dated Oct. 22, 2020, 9 pgs.

(Continued)

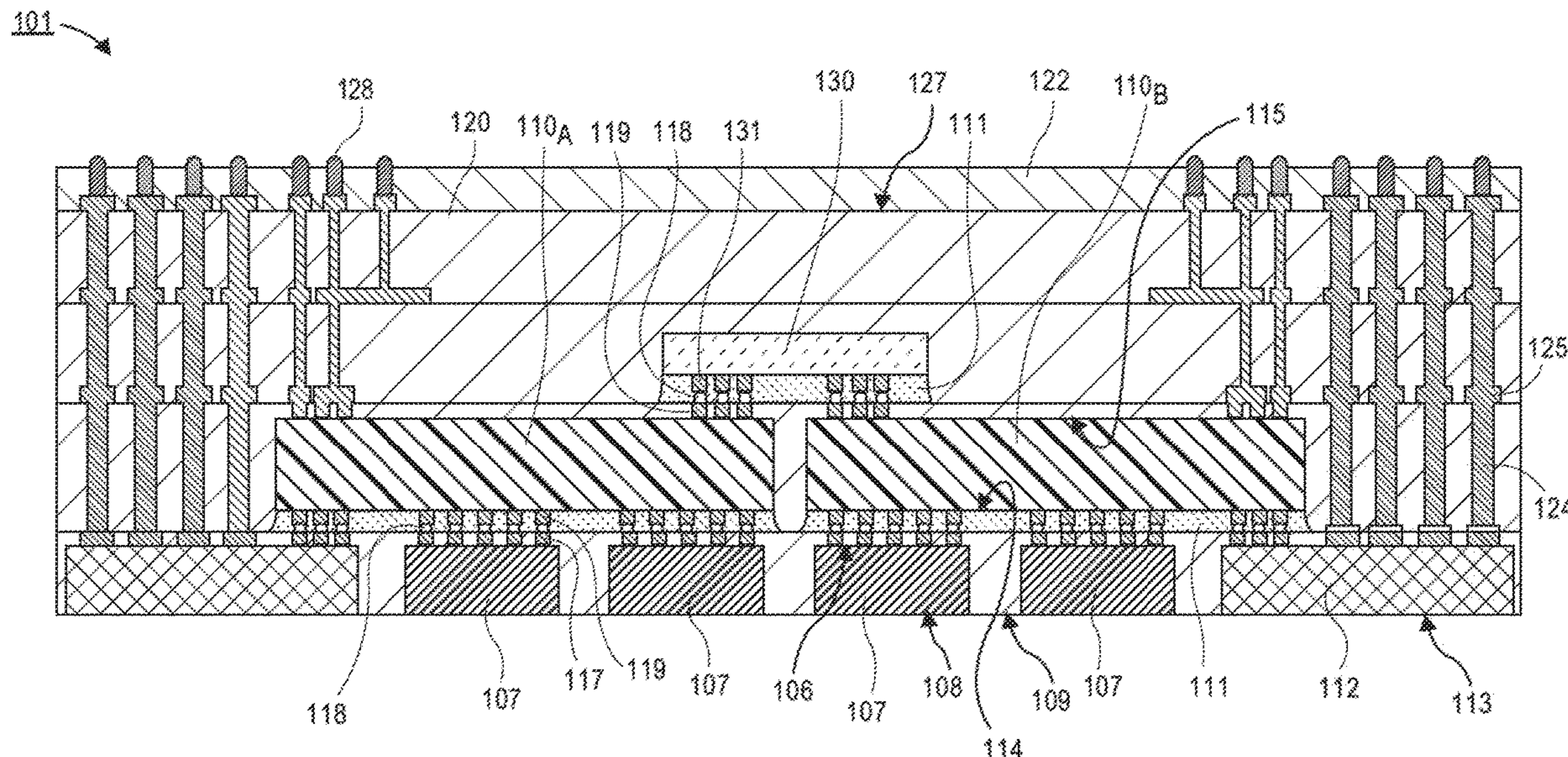
Primary Examiner — Vu A Vu

(74) *Attorney, Agent, or Firm* — Schwabe, Williamson & Wyatt, P.C.

(57) **ABSTRACT**

Embodiments disclosed herein include electronic packages and methods of forming such electronic packages. In an embodiment, the electronic package comprises a mold layer having a first surface and a second surface opposite the first surface, and a plurality of first dies embedded in the mold layer. In an embodiment, each of the plurality of first dies has a surface that is substantially coplanar with the first surface of the mold layer. In an embodiment, the electronic package further comprises a second die embedded in the mold layer. In an embodiment, the second die is positioned between the plurality of first dies and the second surface of the mold layer.

25 Claims, 17 Drawing Sheets



- (51) **Int. Cl.**
H01L 21/48 (2006.01)
H01L 23/31 (2006.01)
H01L 23/538 (2006.01)
- (52) **U.S. Cl.**
 CPC *H01L 21/565* (2013.01); *H01L 21/568* (2013.01); *H01L 23/3121* (2013.01); *H01L 23/5383* (2013.01); *H01L 23/5386* (2013.01); *H01L 23/5389* (2013.01); *H01L 24/19* (2013.01); *H01L 24/20* (2013.01); *H01L 2224/214* (2013.01); *H01L 2924/3511* (2013.01)
- (58) **Field of Classification Search**
 CPC H01L 2924/3511; H01L 25/0652; H01L 25/50; H01L 23/5385; H01L 24/16; H01L 24/96; H01L 25/03; H01L 2224/04105; H01L 2224/12105; H01L 2224/16145; H01L 2224/16227; H01L 2224/16235; H01L 2224/17181; H01L 2224/32145; H01L 2224/32225; H01L 2224/73204; H01L 2224/73259; H01L 2224/81005; H01L 2224/83005; H01L 2224/92125; H01L 2224/92224; H01L 2225/06513; H01L 2225/06517; H01L 2225/06524; H01L 2924/15311; H01L 2924/18161; H01L 2924/18162; H01L 2224/18; H01L 25/18; H01L 23/3107; H01L 23/31; H01L 23/481; H01L 23/528; H01L 25/0657
 USPC 257/668
 See application file for complete search history.

10,504,847	B2 *	12/2019	Chang	H01L 21/568
10,510,721	B2	12/2019	Bhagavat		
10,593,628	B2	3/2020	Bhagavat		
10,651,126	B2 *	5/2020	Hsiung	H01L 23/5384
10,720,401	B2 *	7/2020	Ting	H01L 24/20
10,867,954	B2 *	12/2020	Ting	H01L 23/5385
11,088,124	B2	8/2021	Chen		
11,289,424	B2	3/2022	Wu		
2014/0159228	A1	6/2014	Teh		
2016/0071818	A1	3/2016	Wang et al.		
2017/0125379	A1 *	5/2017	Chen	H01L 21/4853
2019/0043792	A1	2/2019	Weerasekera		
2020/0006232	A1	1/2020	Pietambaram		

FOREIGN PATENT DOCUMENTS

WO	WO 2018/125132	7/2018
WO	WO 2019/199428	10/2019
WO	WO 2020/005392	1/2020

OTHER PUBLICATIONS

Office Action from European Patent Application No. 20174455.4, dated Jan. 14, 2022, 5 pgs.
 Office Action from European Patent Application No. 20174455.4, dated Sep. 30, 2022, 9 pgs.
 Search Report from European Patent Application No. 20156400.2, dated Jun. 18, 2020, 11 pgs.
 Search Report from European Patent Application No. 21198092.5, dated Feb. 1, 2022, 10 pgs.
 Office Action for U.S. Appl. No. 17/556,667 dated Nov. 30, 2022, 28 pgs.
 Office Action for U.S. Appl. No. 17/716,947 dated Dec. 23, 2022, 23 pgs.
 Final Office Action for U.S. Appl. No. 17/556,667 dated Apr. 5, 2023, 25 pgs.
 Final Office Action for U.S. Appl. No. 17/716,947 dated Apr. 5, 2023, 26 pgs.
 Office Action for Taiwan Patent Application No. 109100796 dated Jan. 10, 2023, 33 pgs., with English translation.
 Office Action for Taiwan Patent Application No. 110130795 dated Jan. 10, 2023, 22 pgs., with English translation.
 Office Action for Taiwan Patent Application No. 111118269 dated Jan. 10, 2023, 15 pgs., with English translation.
 Extended European Search Report for European Patent Application No. 22170377.0, dated Aug. 23, 2022, 14 pgs.

(56) **References Cited**

U.S. PATENT DOCUMENTS

9,275,955	B2 *	3/2016	Mahajan	H01L 25/165
9,418,924	B2 *	8/2016	Woychik	H01L 25/0657
9,595,496	B2 *	3/2017	Lee	H01L 23/5384
9,627,365	B1 *	4/2017	Yu	H01L 23/28
9,666,559	B2 *	5/2017	Wang	H01L 25/0655
9,831,170	B2 *	11/2017	Scanlan	H01L 24/96
10,008,439	B2 *	6/2018	Zhao	H01L 21/4857
10,217,720	B2 *	2/2019	Wang	H01L 23/3135
10,312,220	B2 *	6/2019	Hiner	H01L 24/17
10,453,802	B2	10/2019	Hu		

* cited by examiner

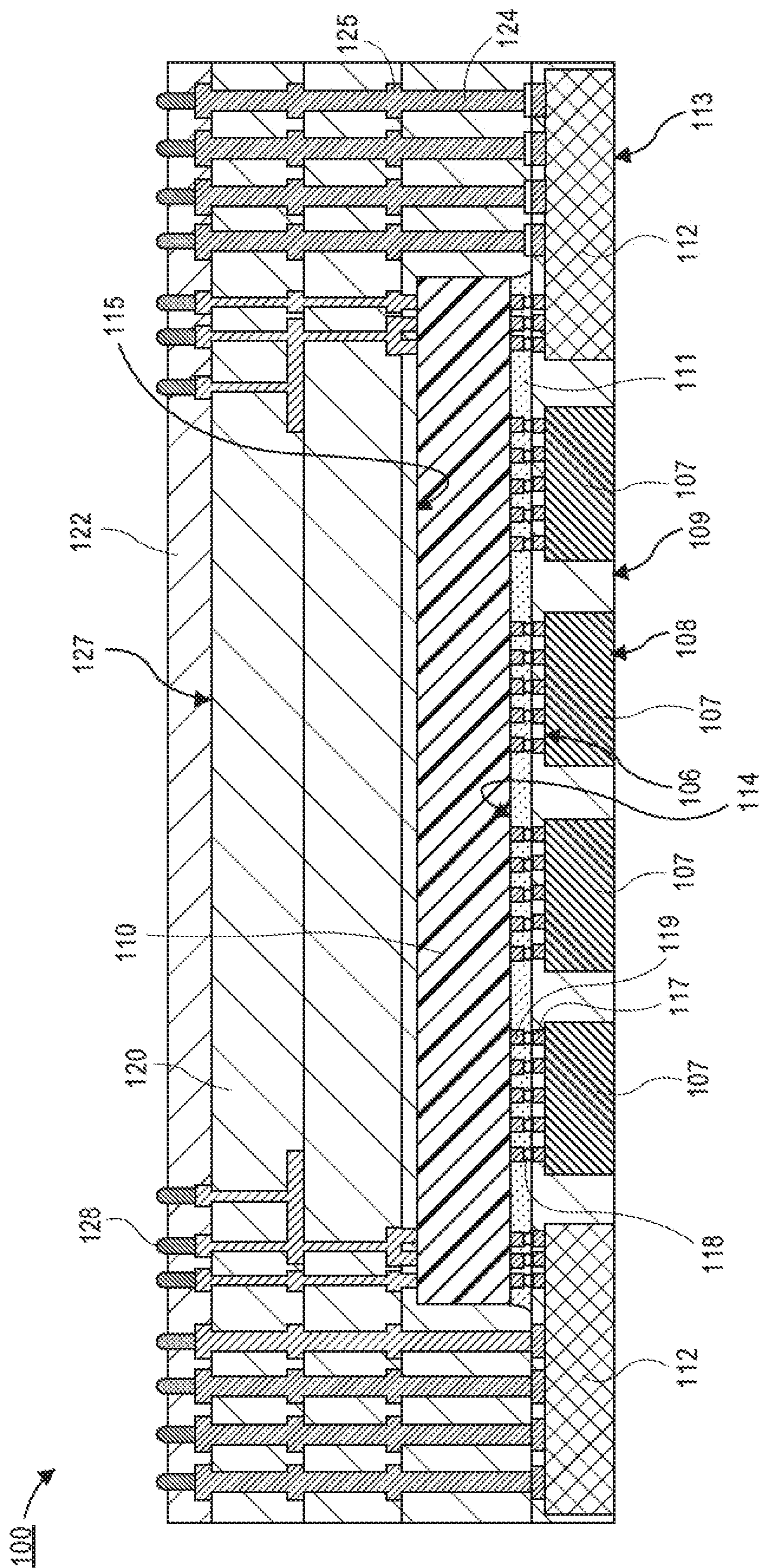


FIG. 1A

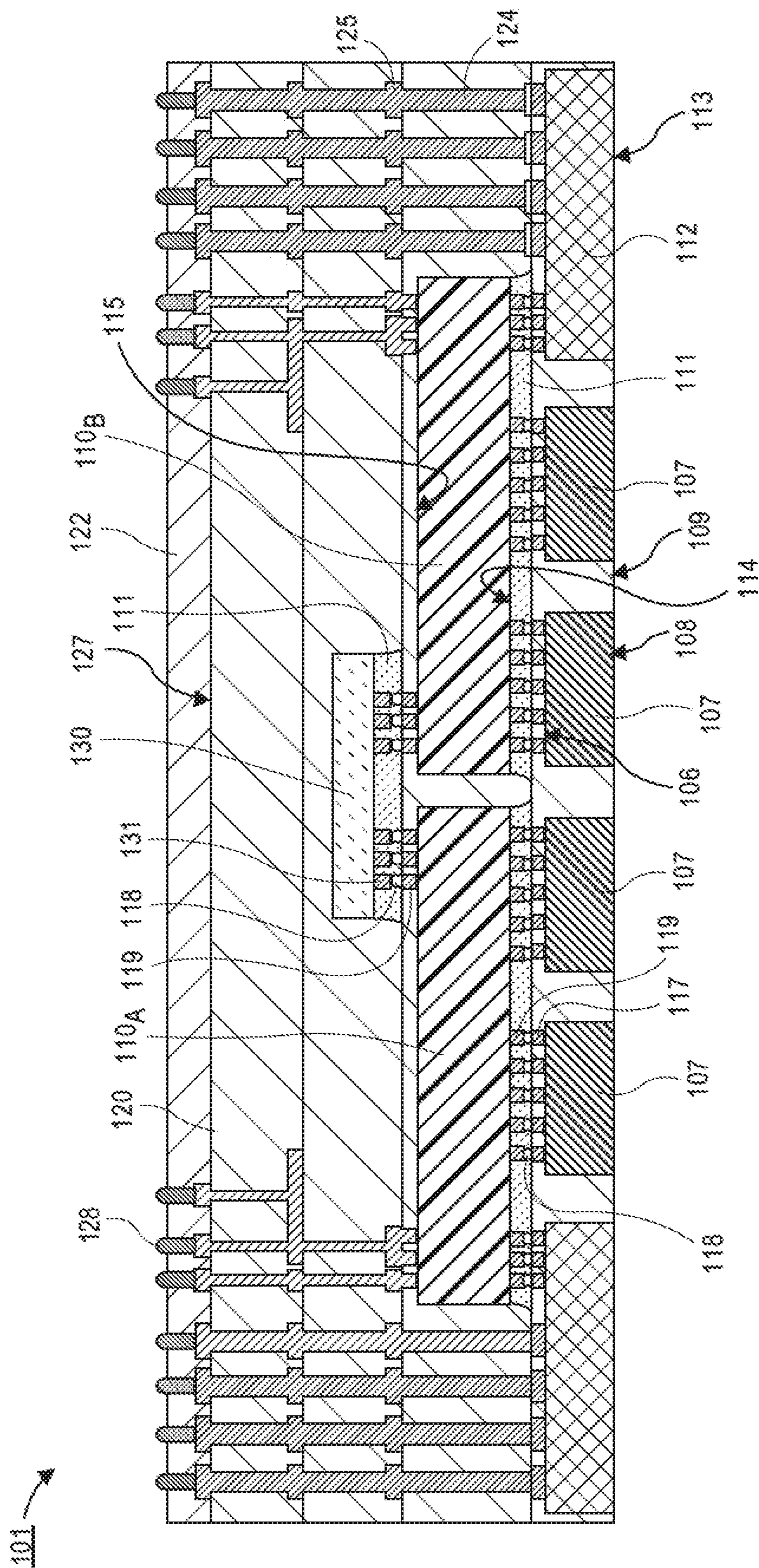


FIG. 1B

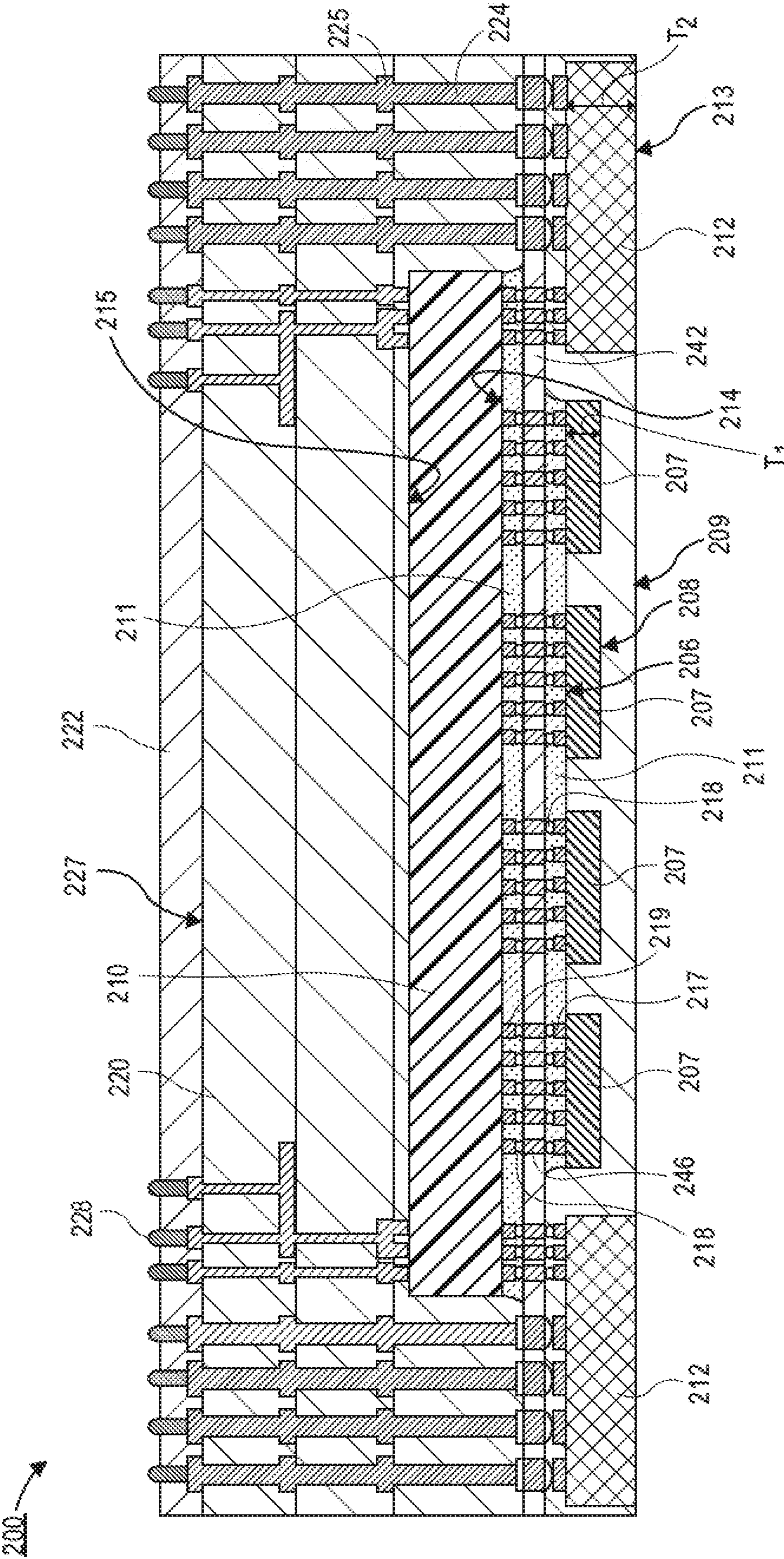


FIG. 2A

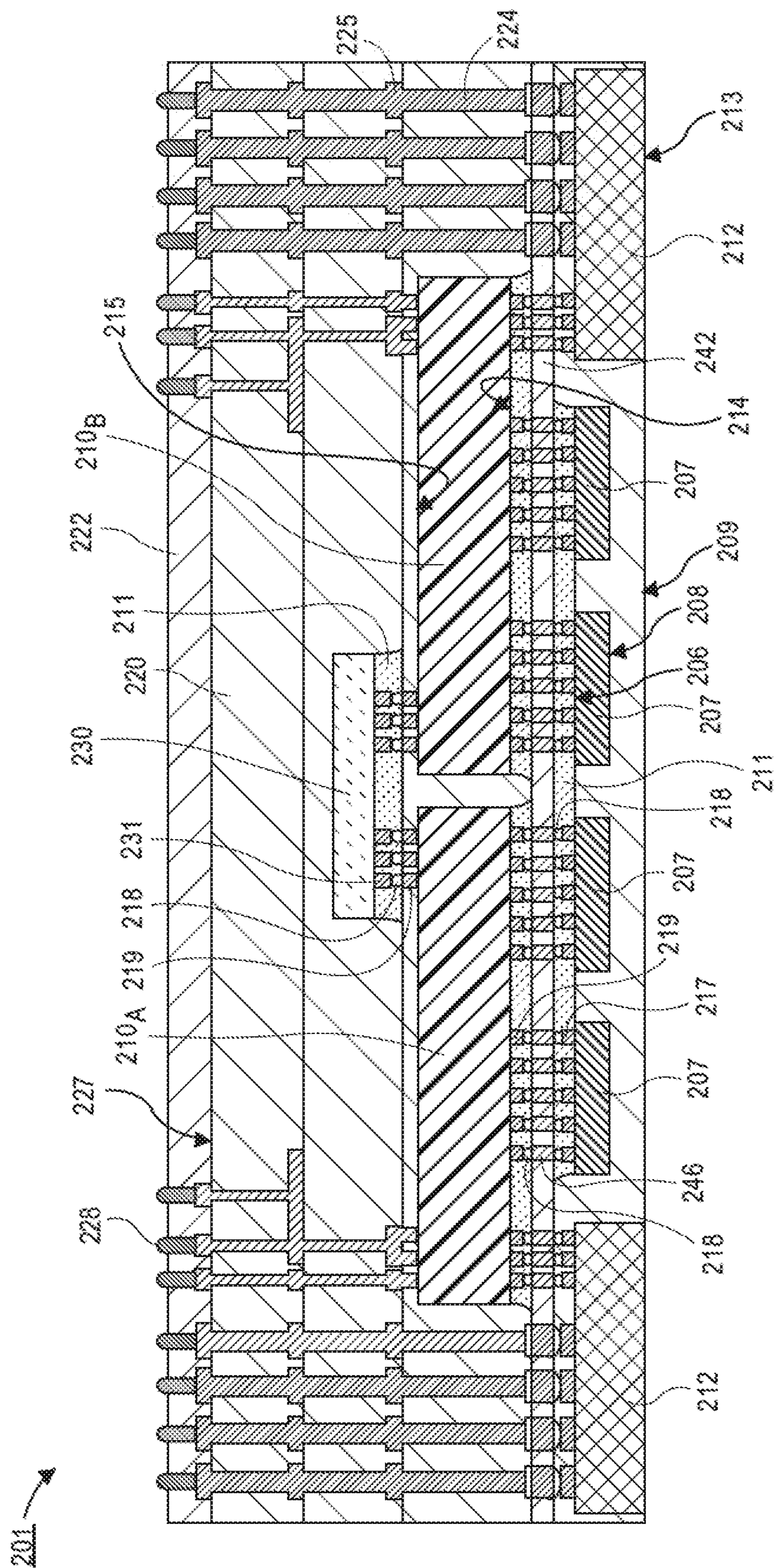


FIG. 2B

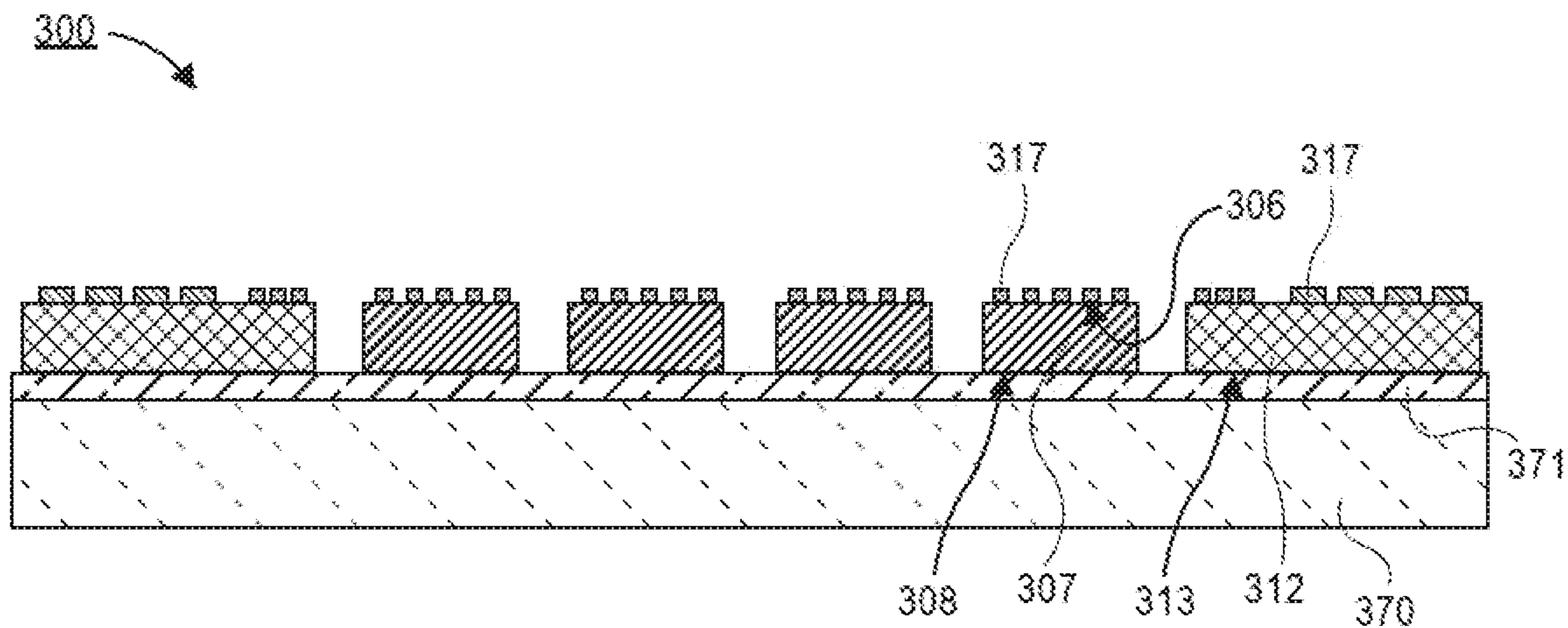


FIG. 3A

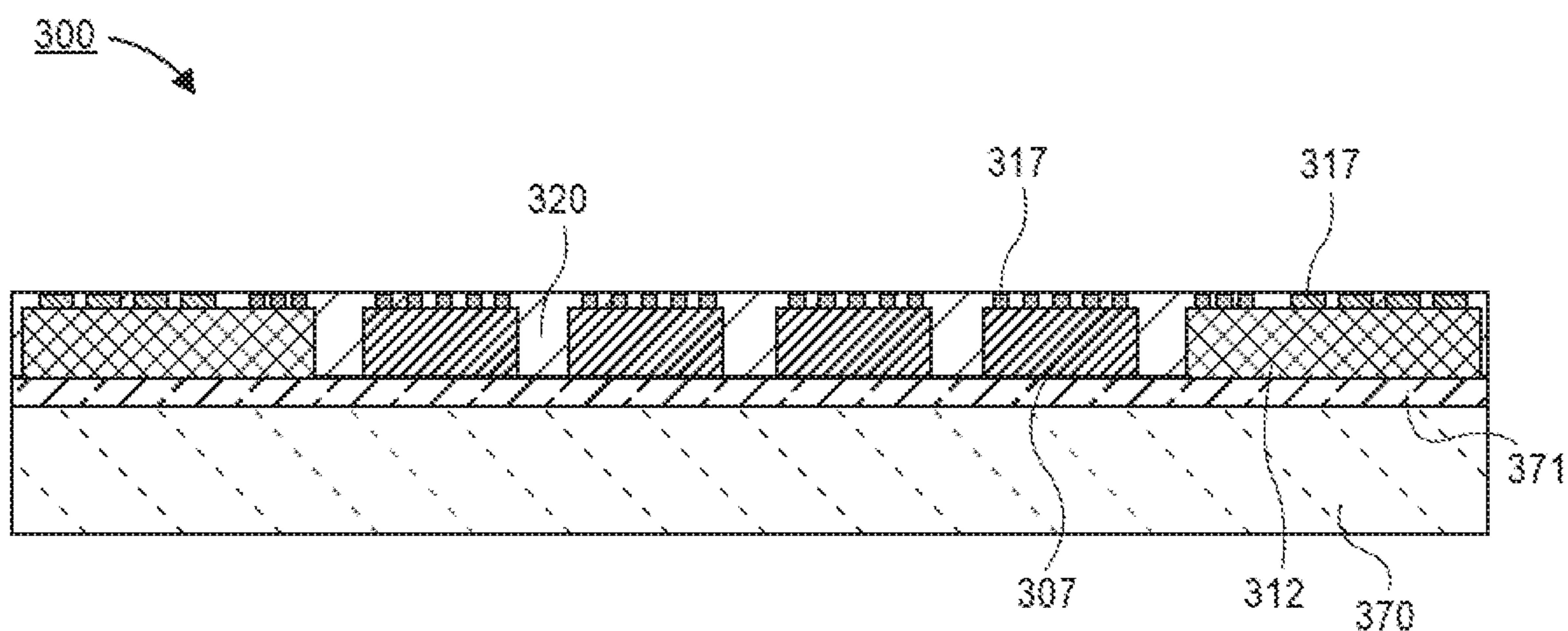


FIG. 3B

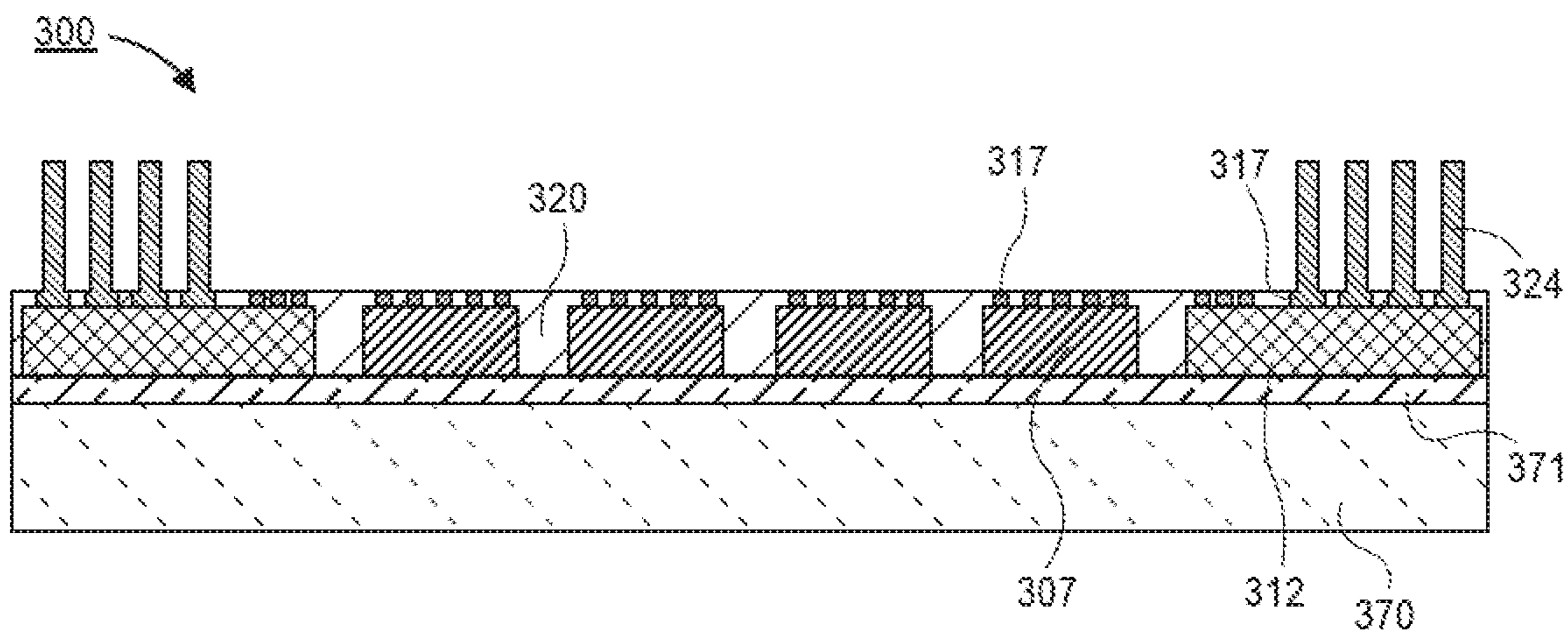


FIG. 3C

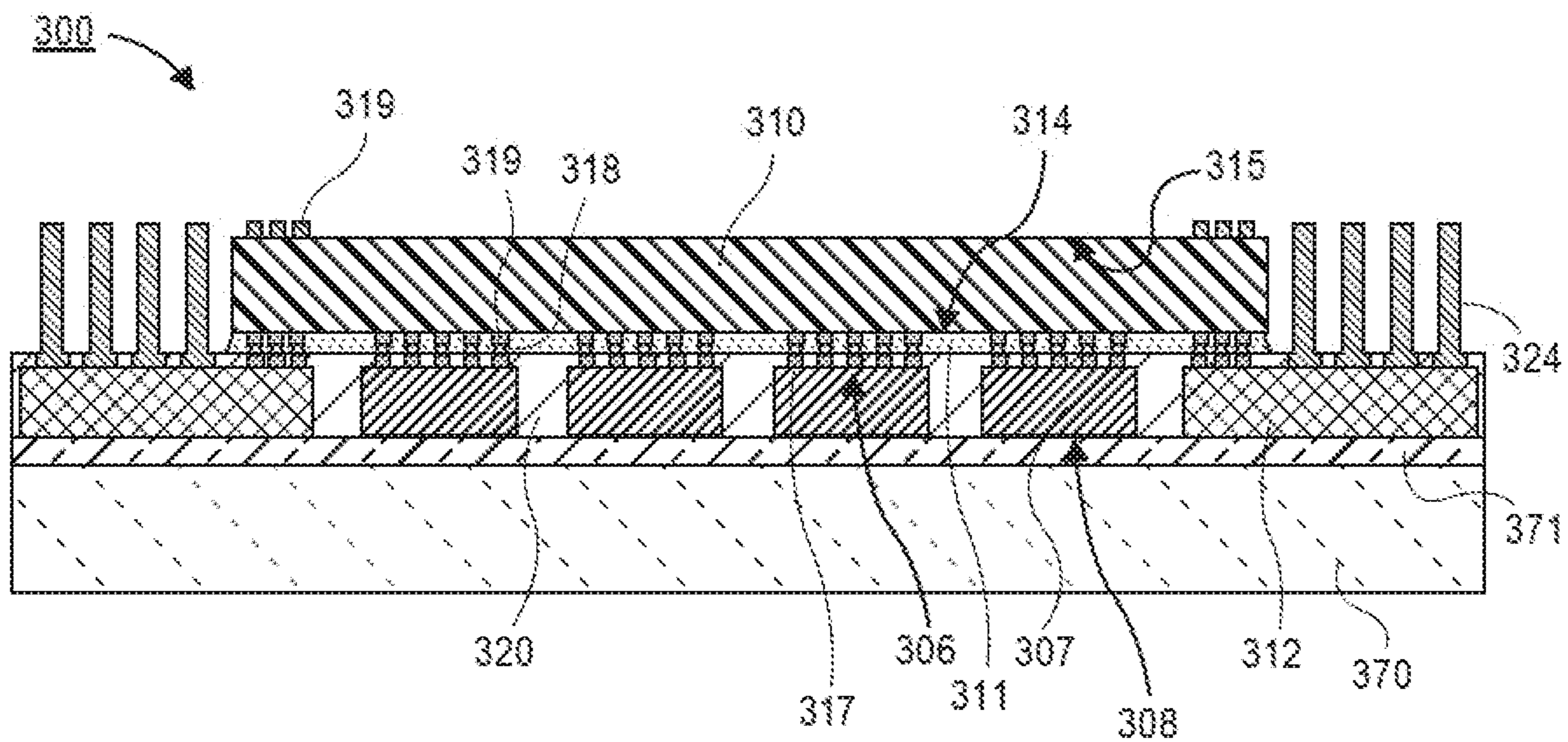


FIG. 3D

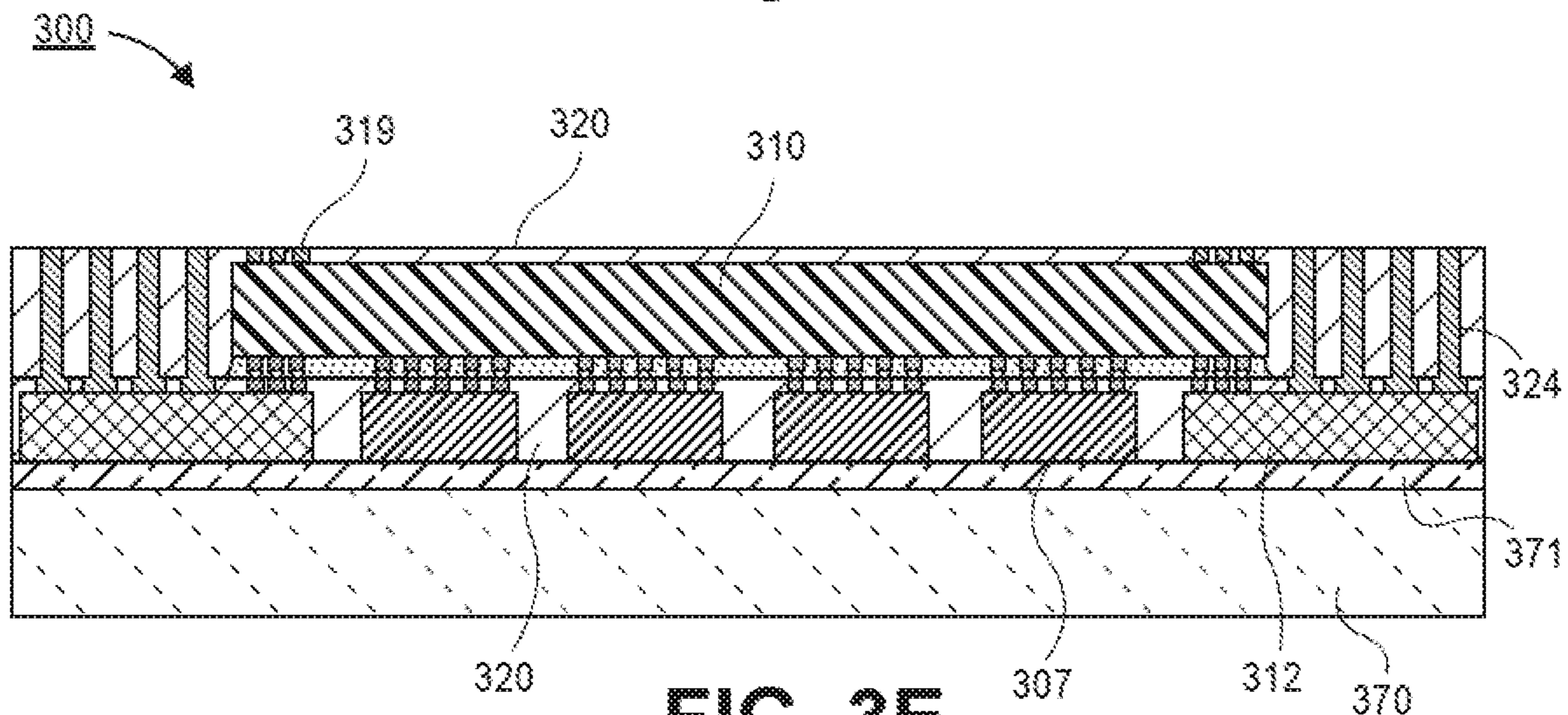


FIG. 3E

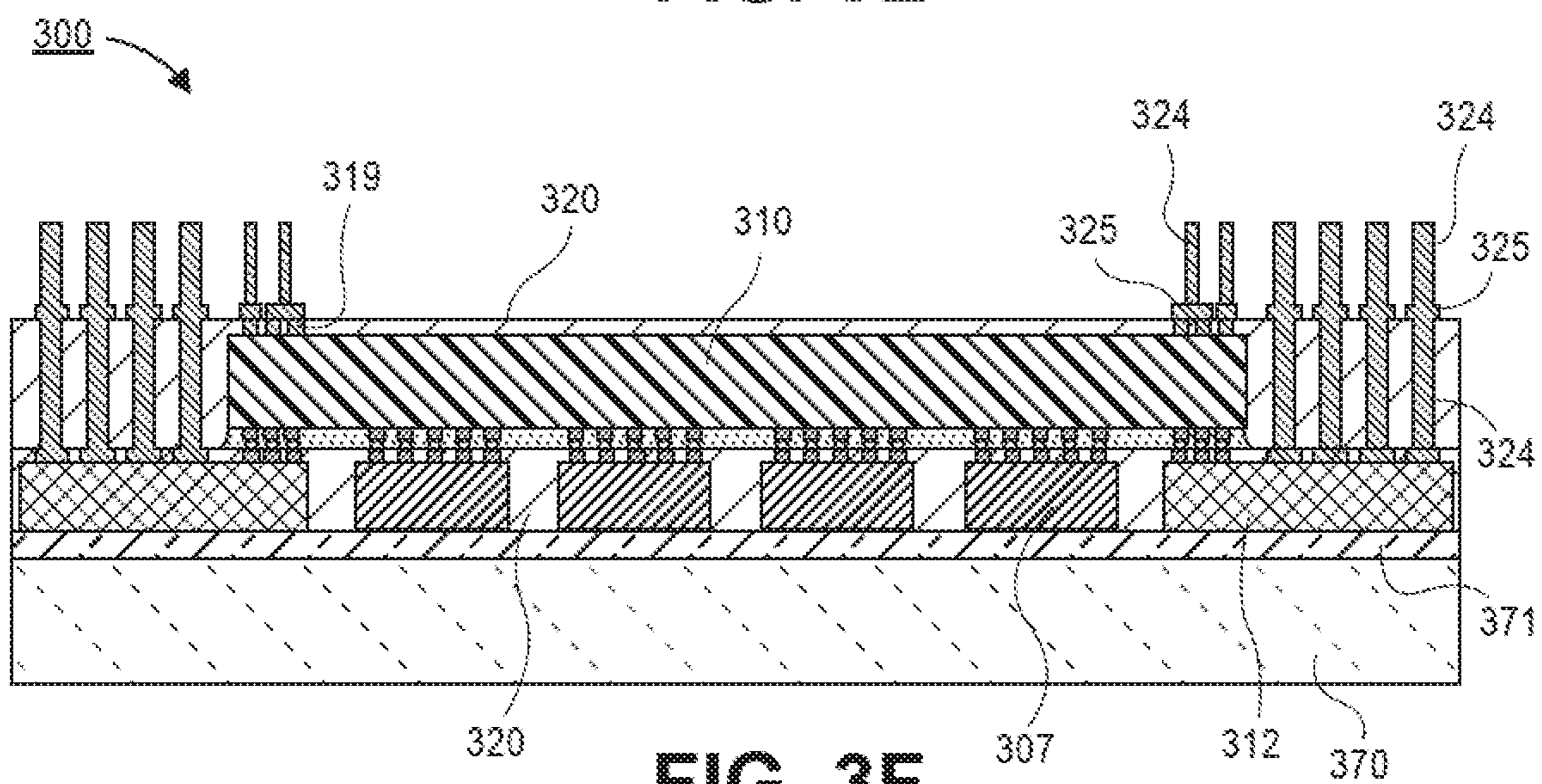


FIG. 3F

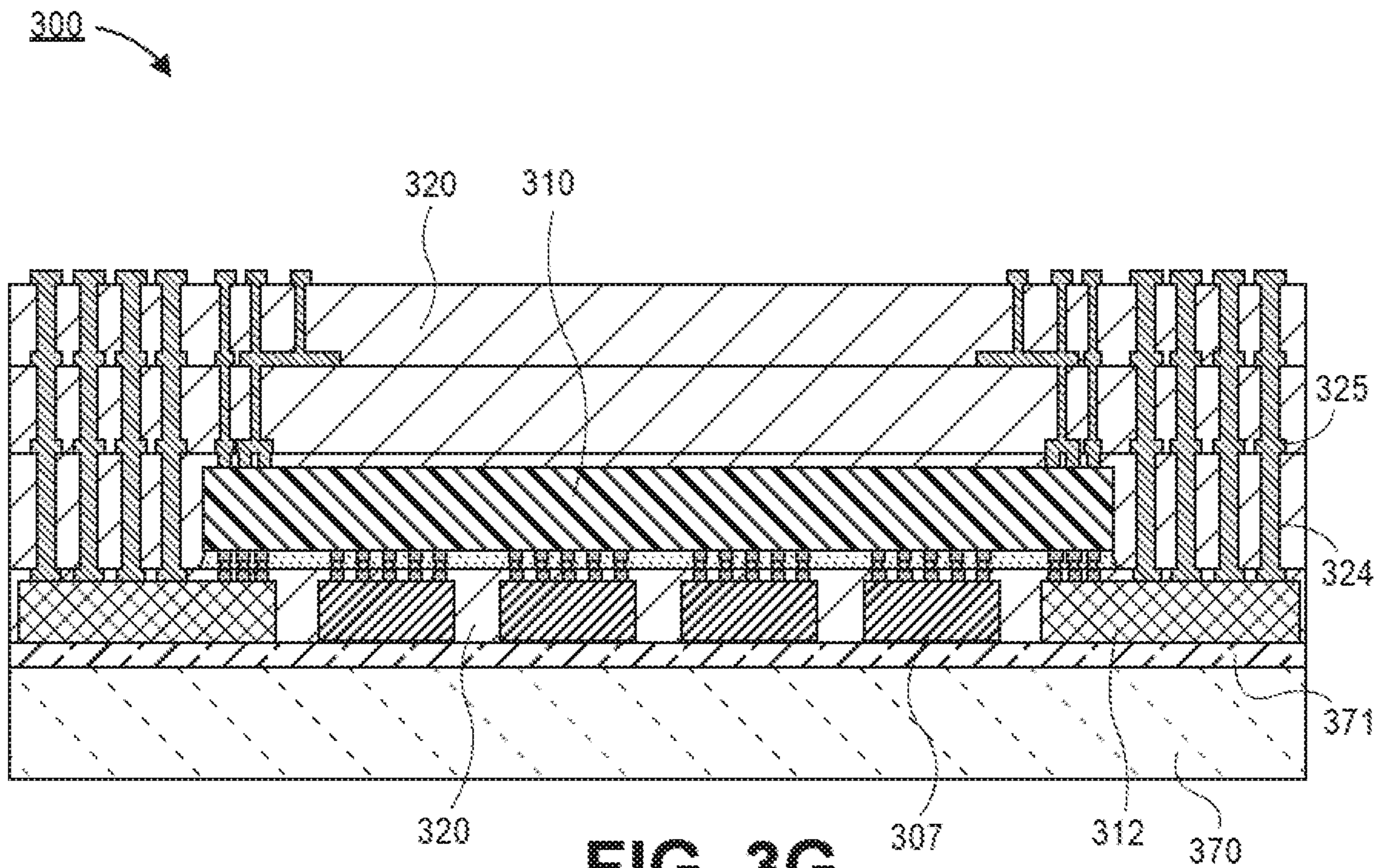


FIG. 3G

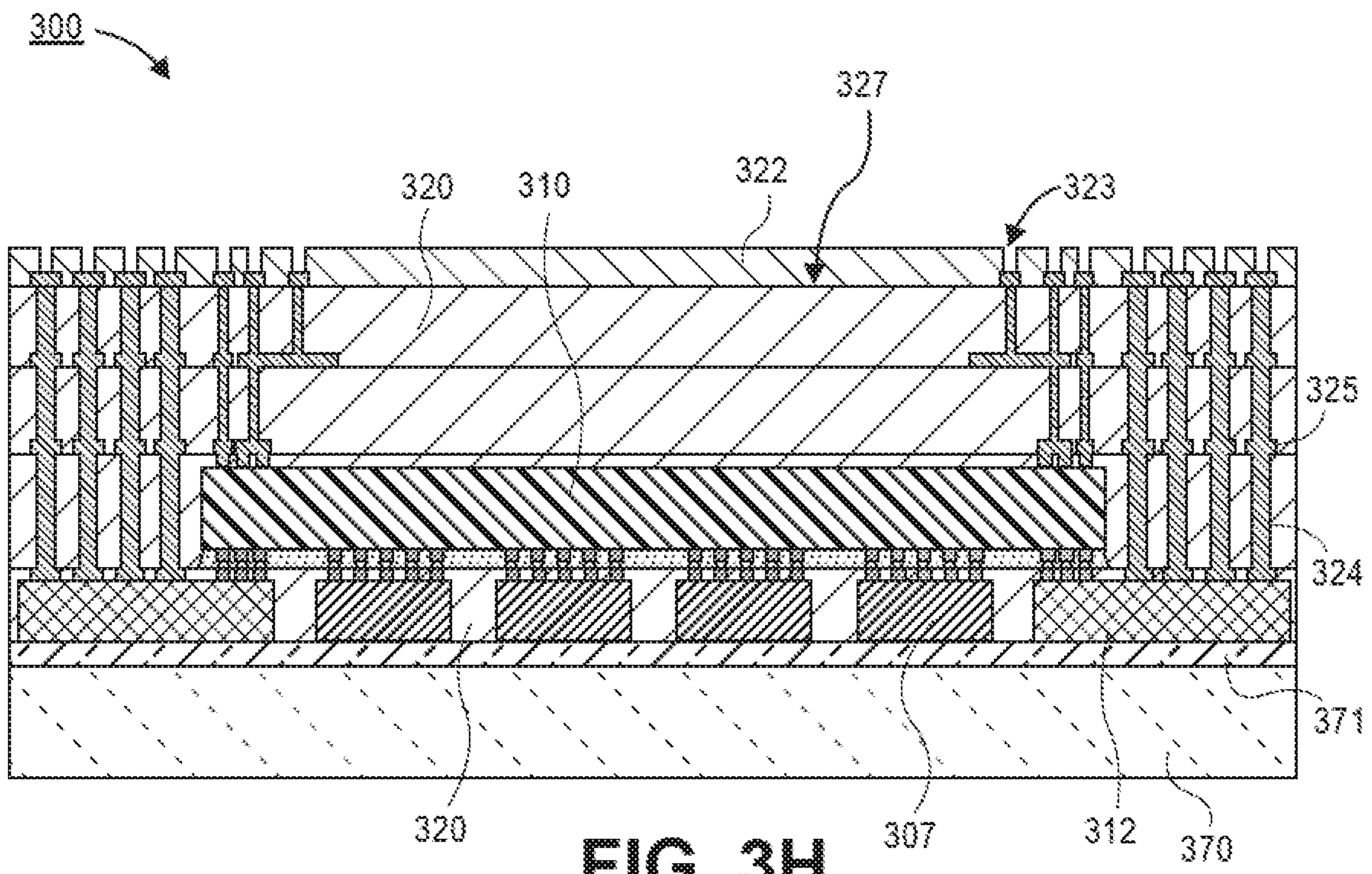
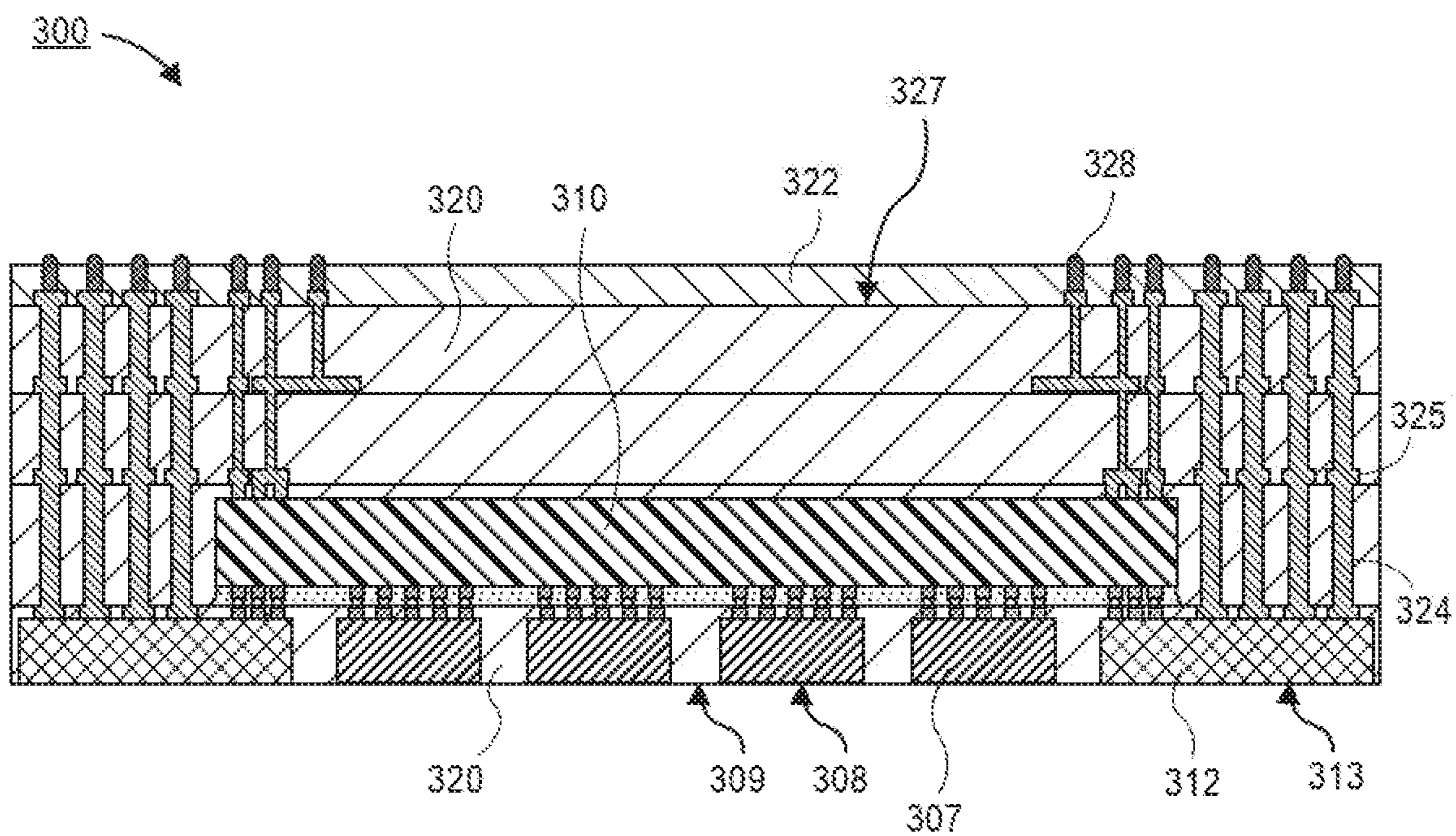
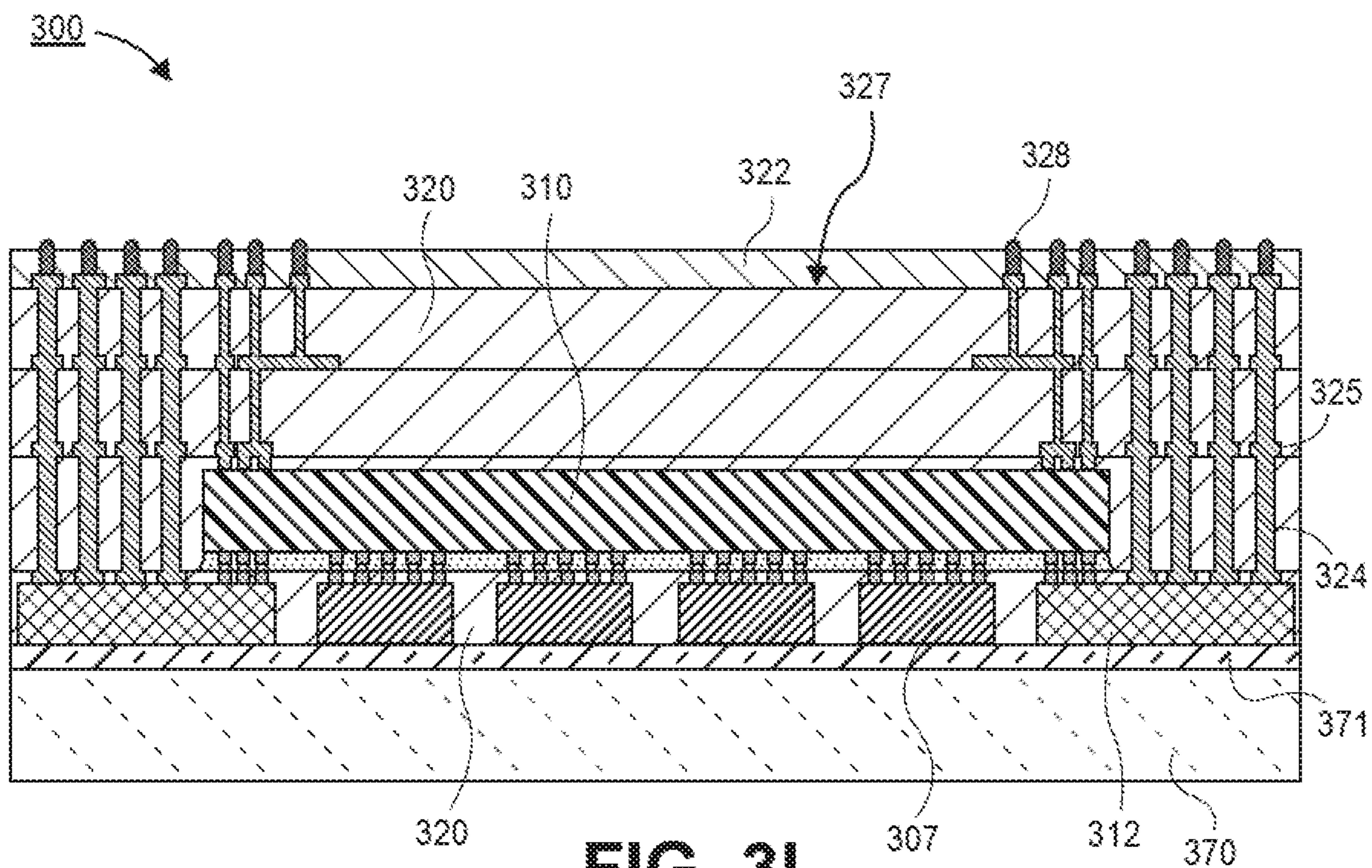


FIG. 3H



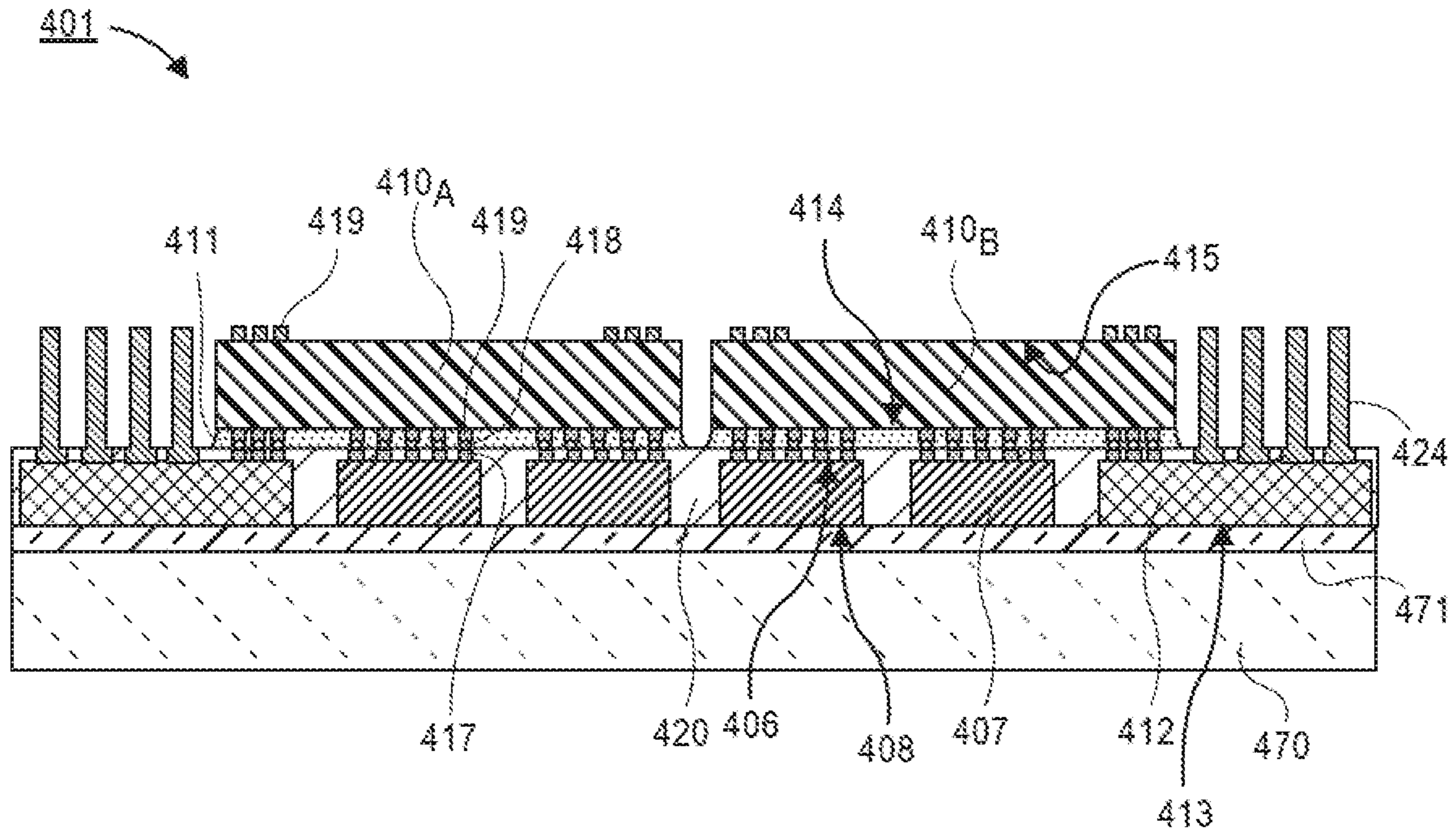


FIG. 4A

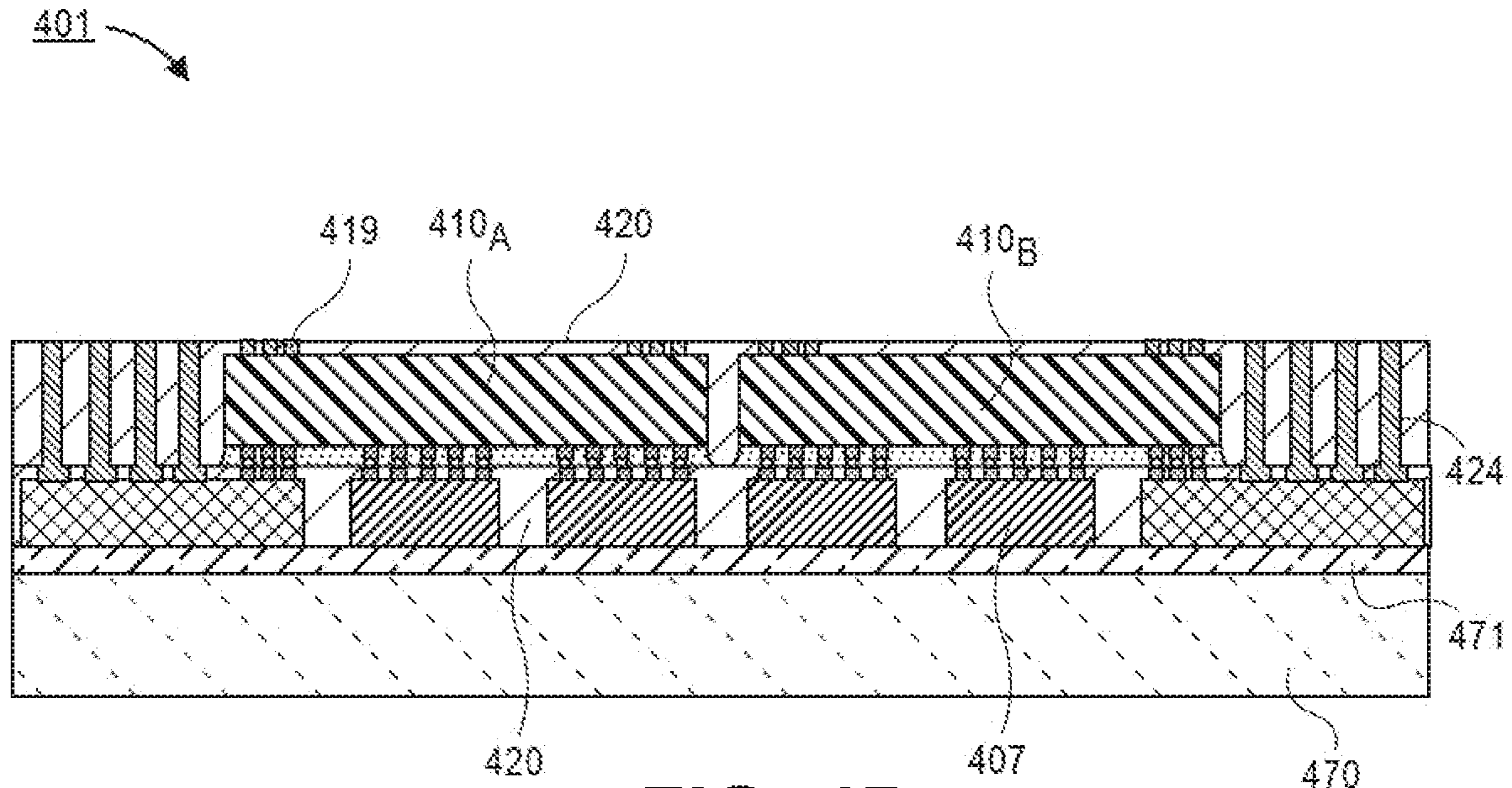


FIG. 4B

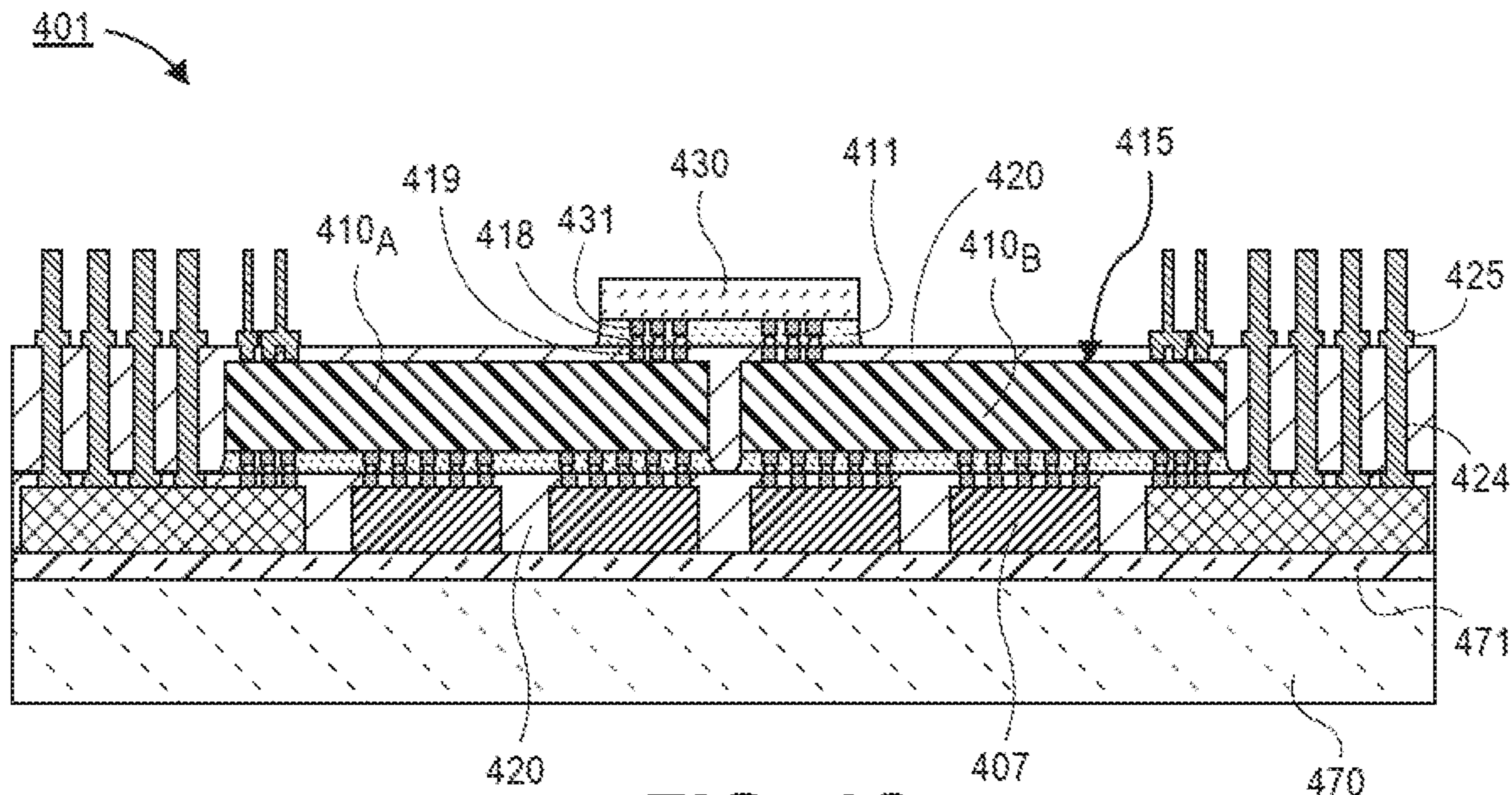


FIG. 4C

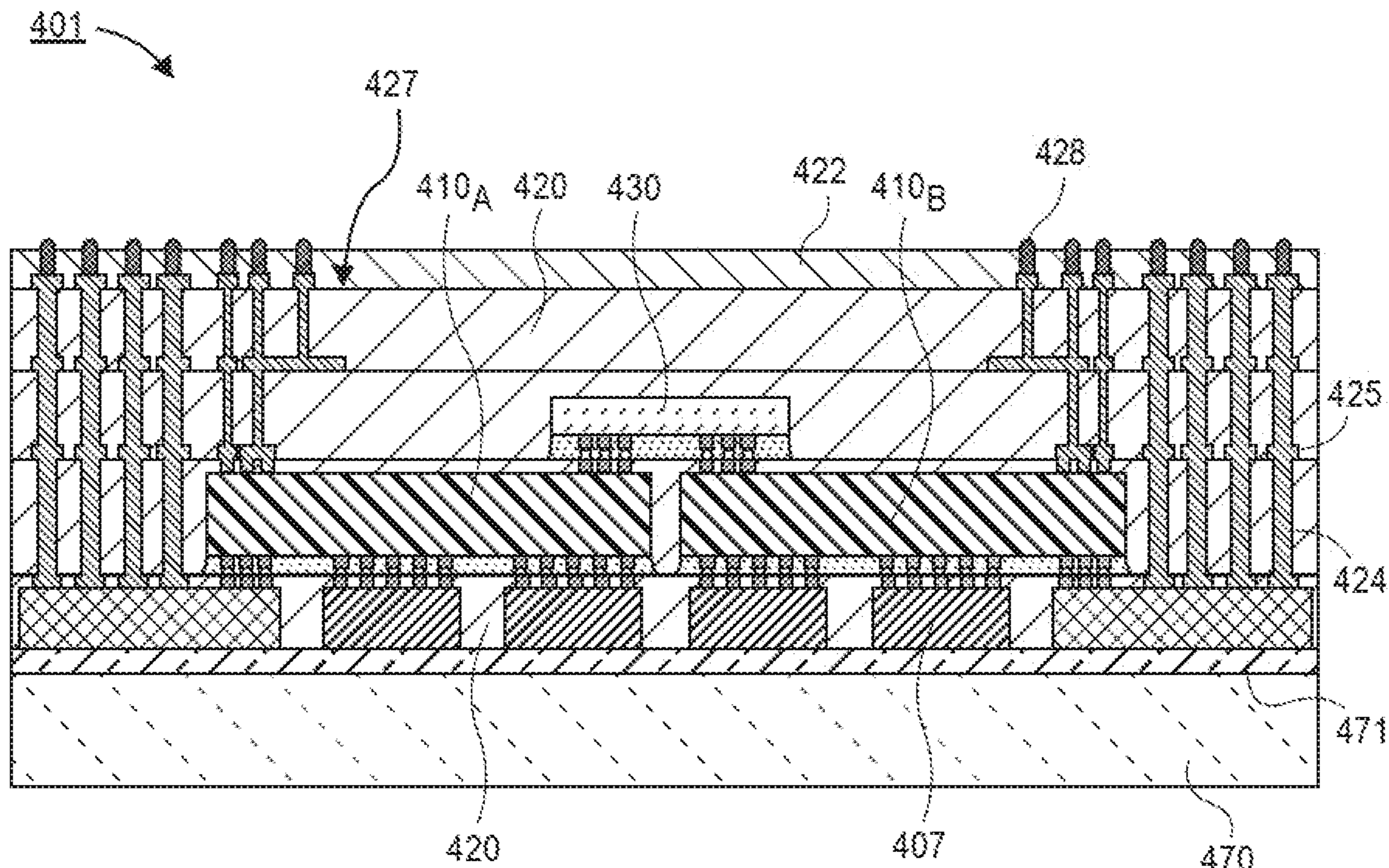


FIG. 4D

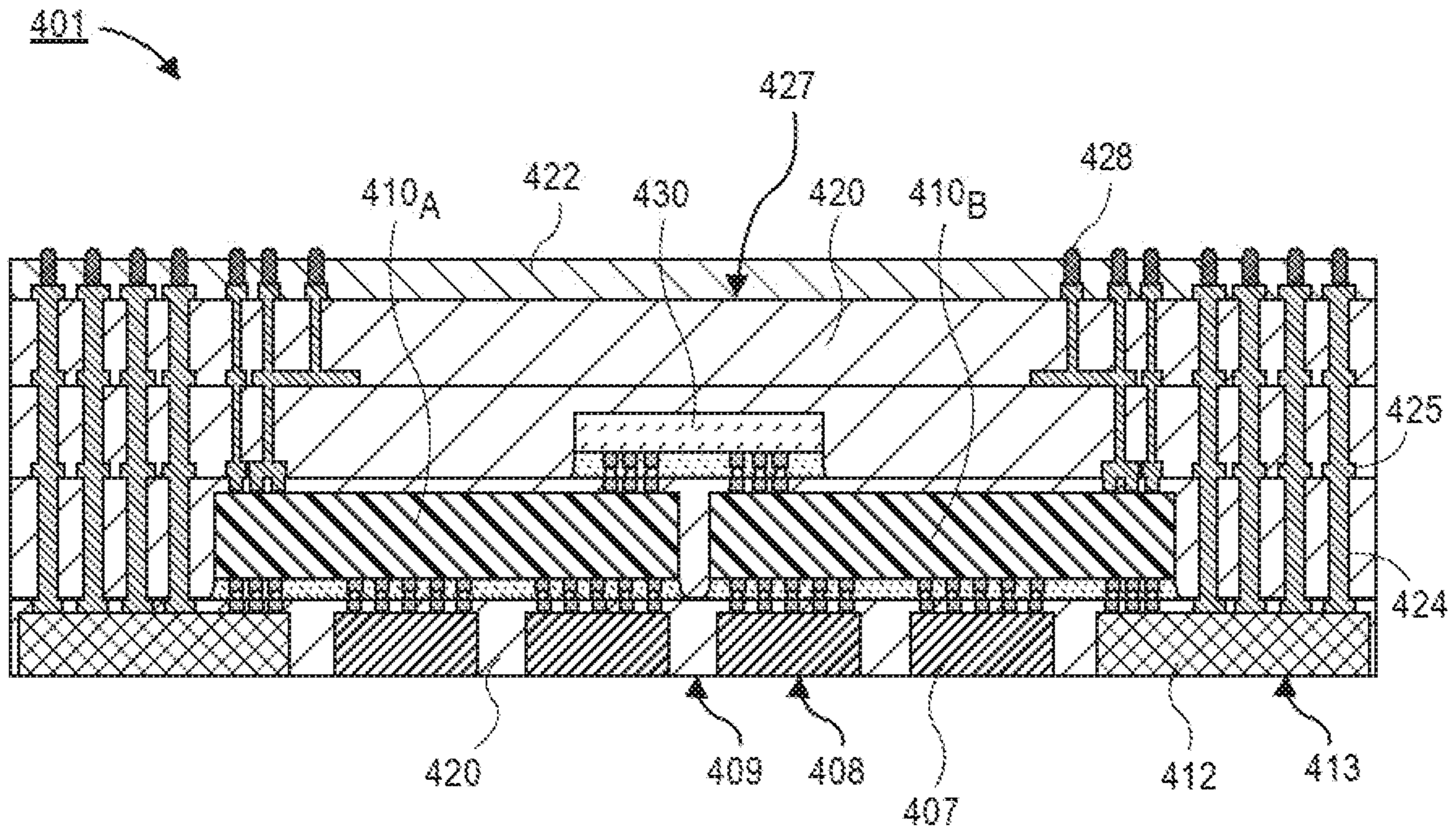


FIG. 4E

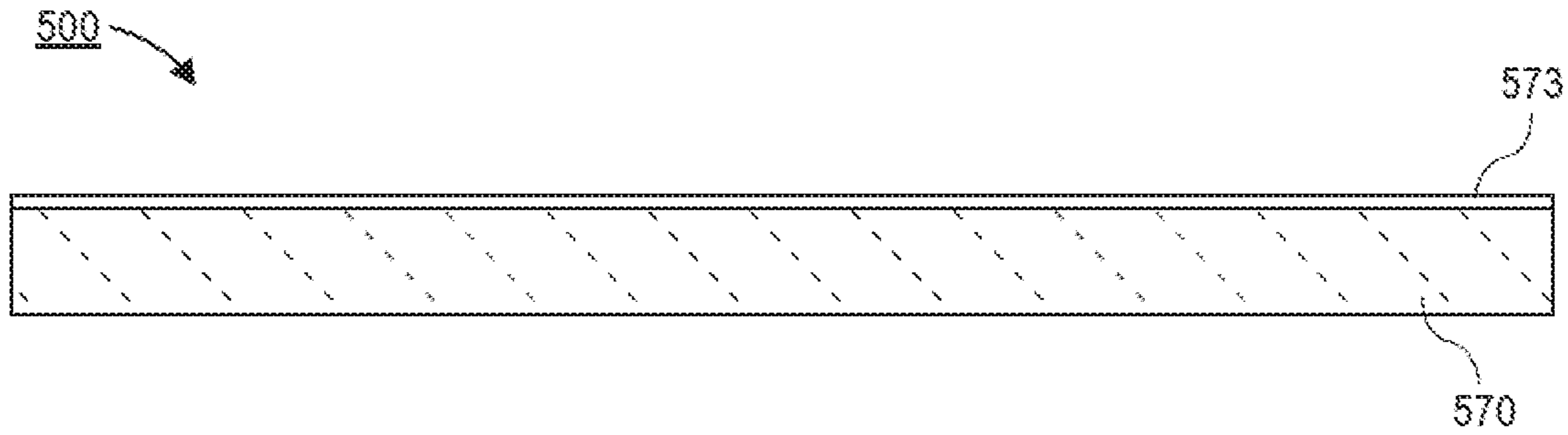


FIG. 5A

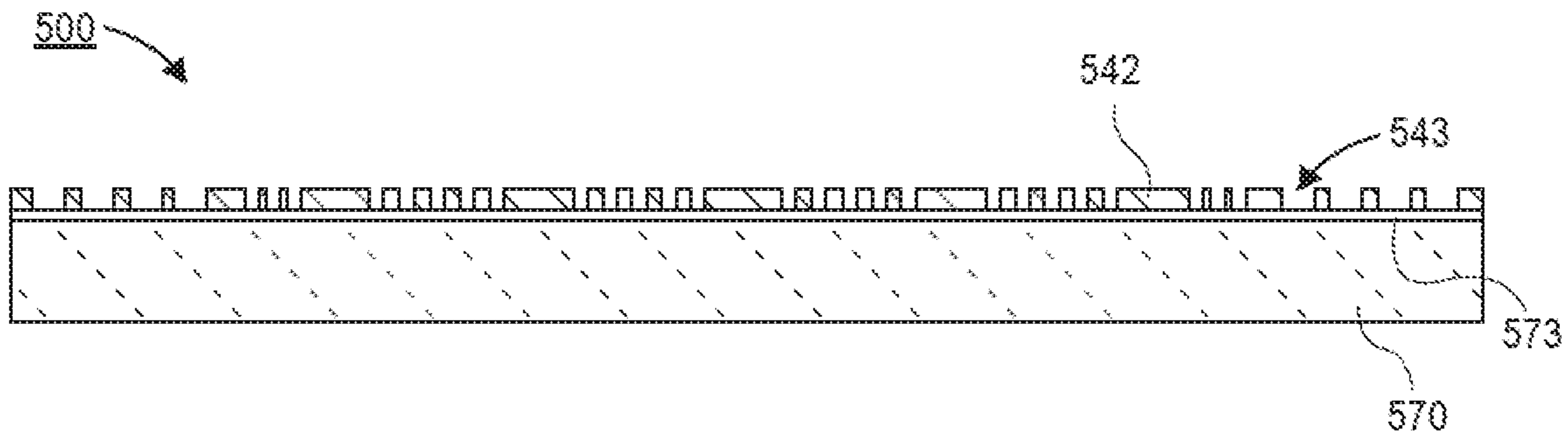


FIG. 5B

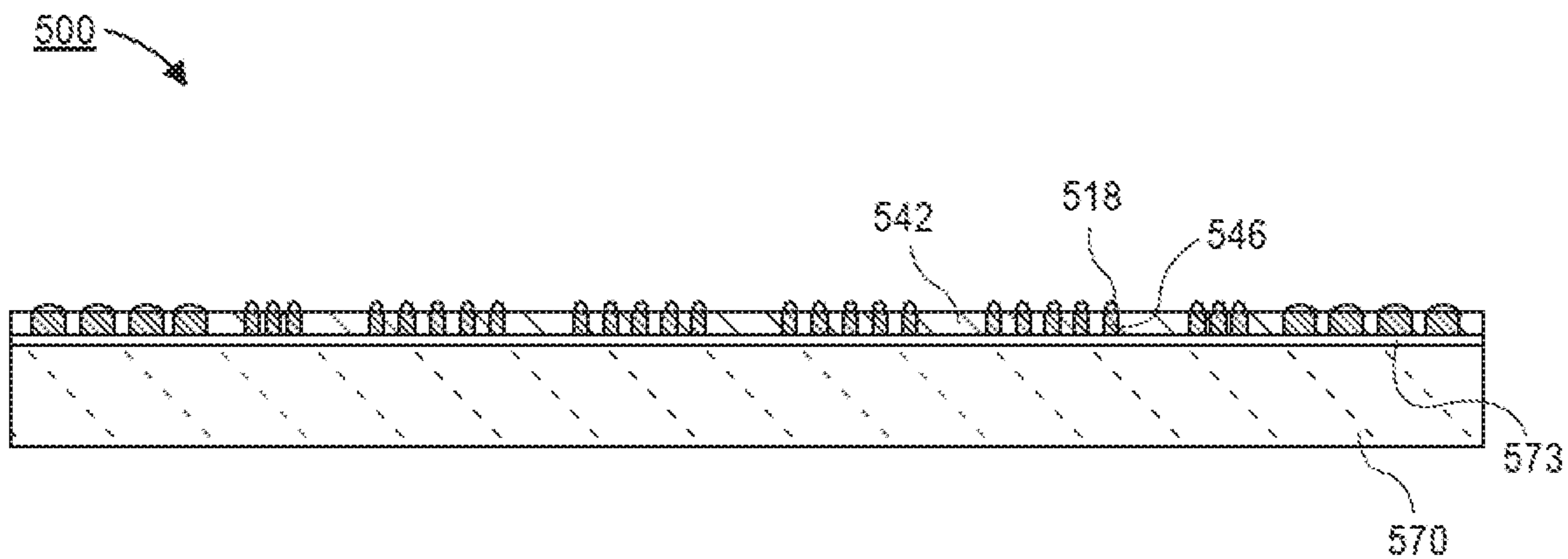


FIG. 5C

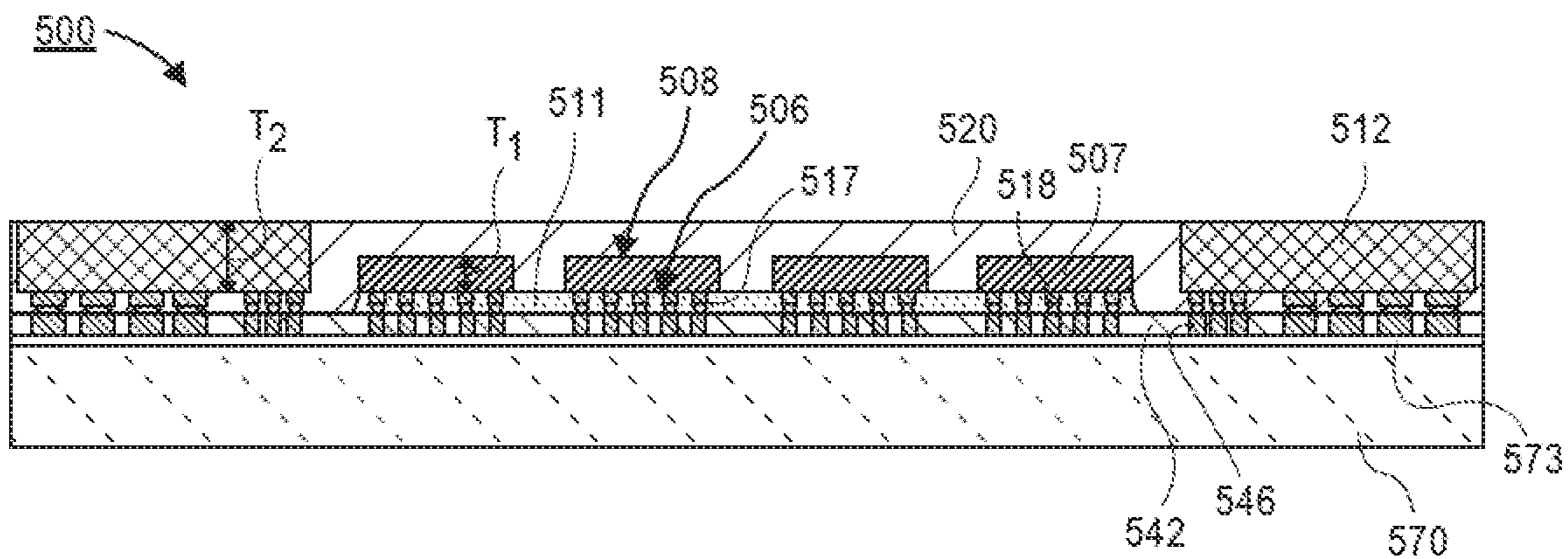


FIG. 5D

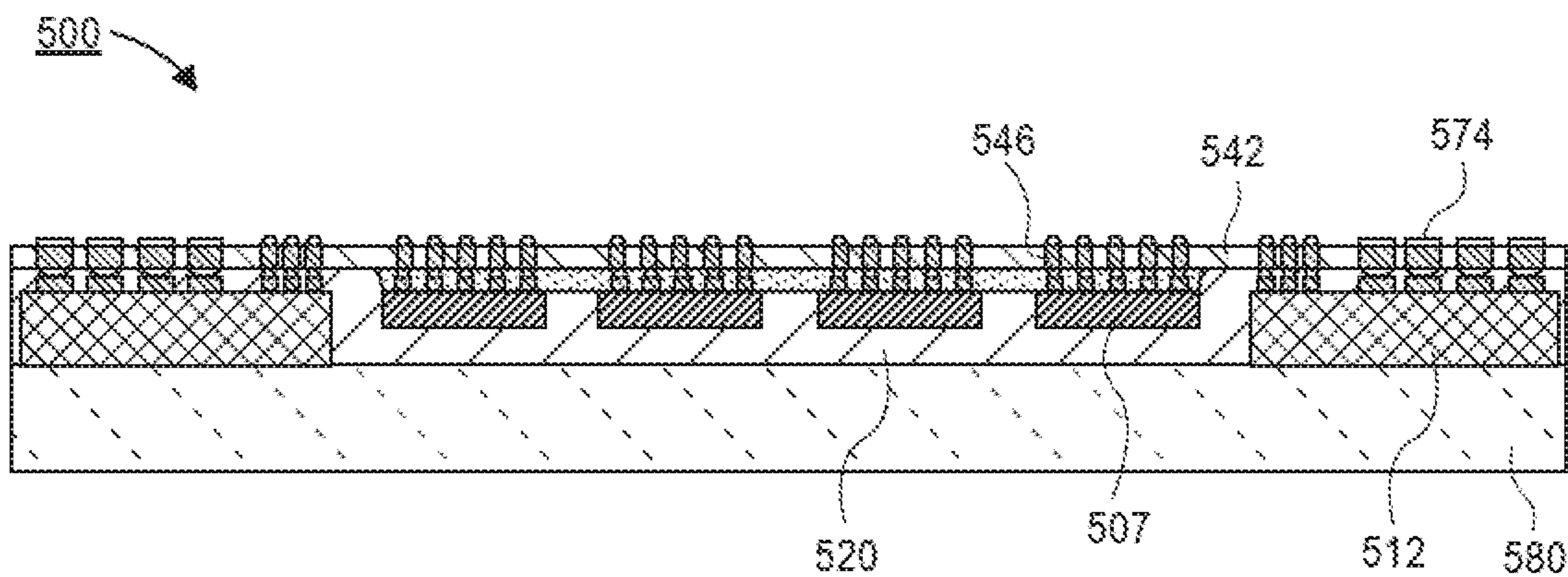


FIG. 5E

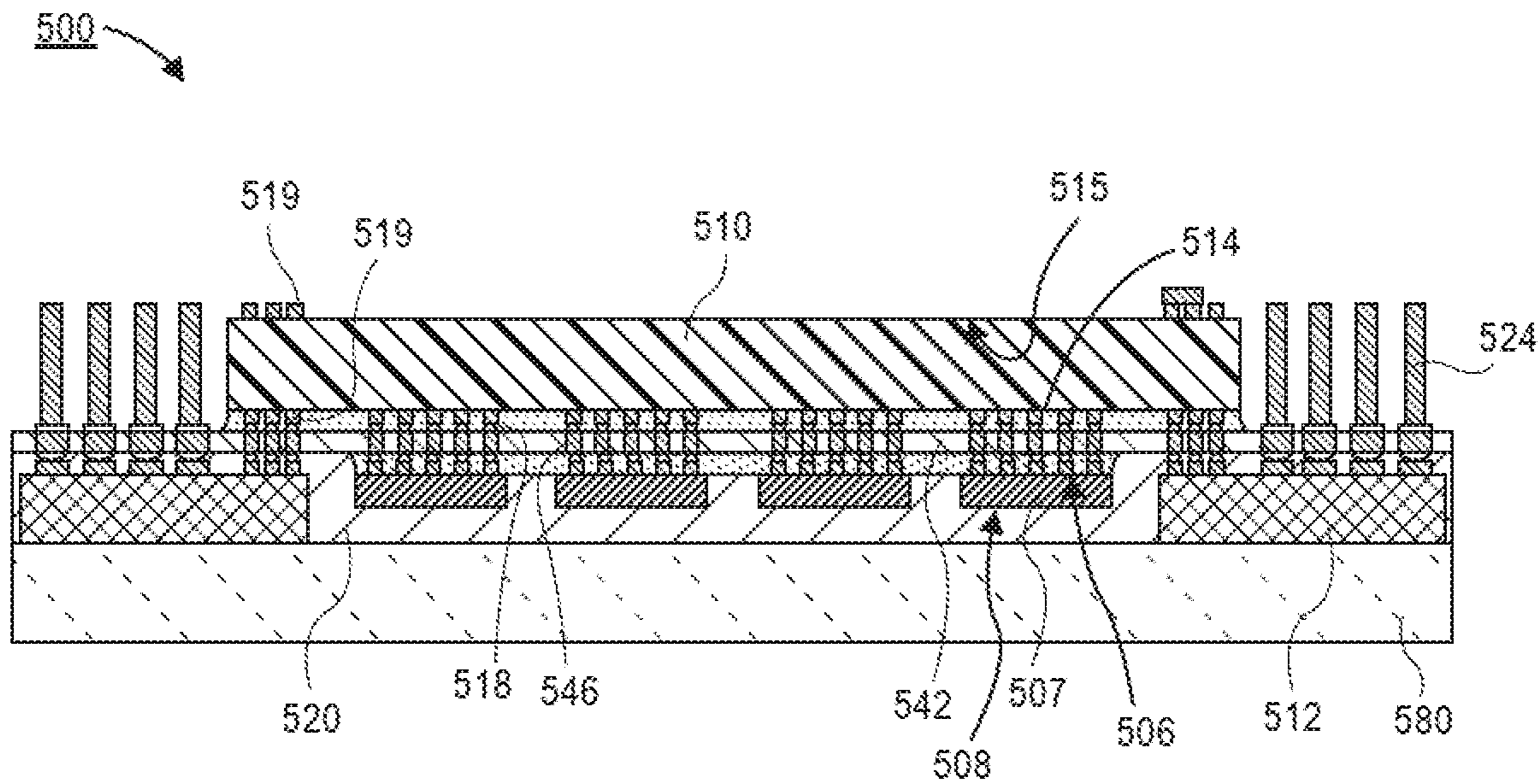


FIG. 5F

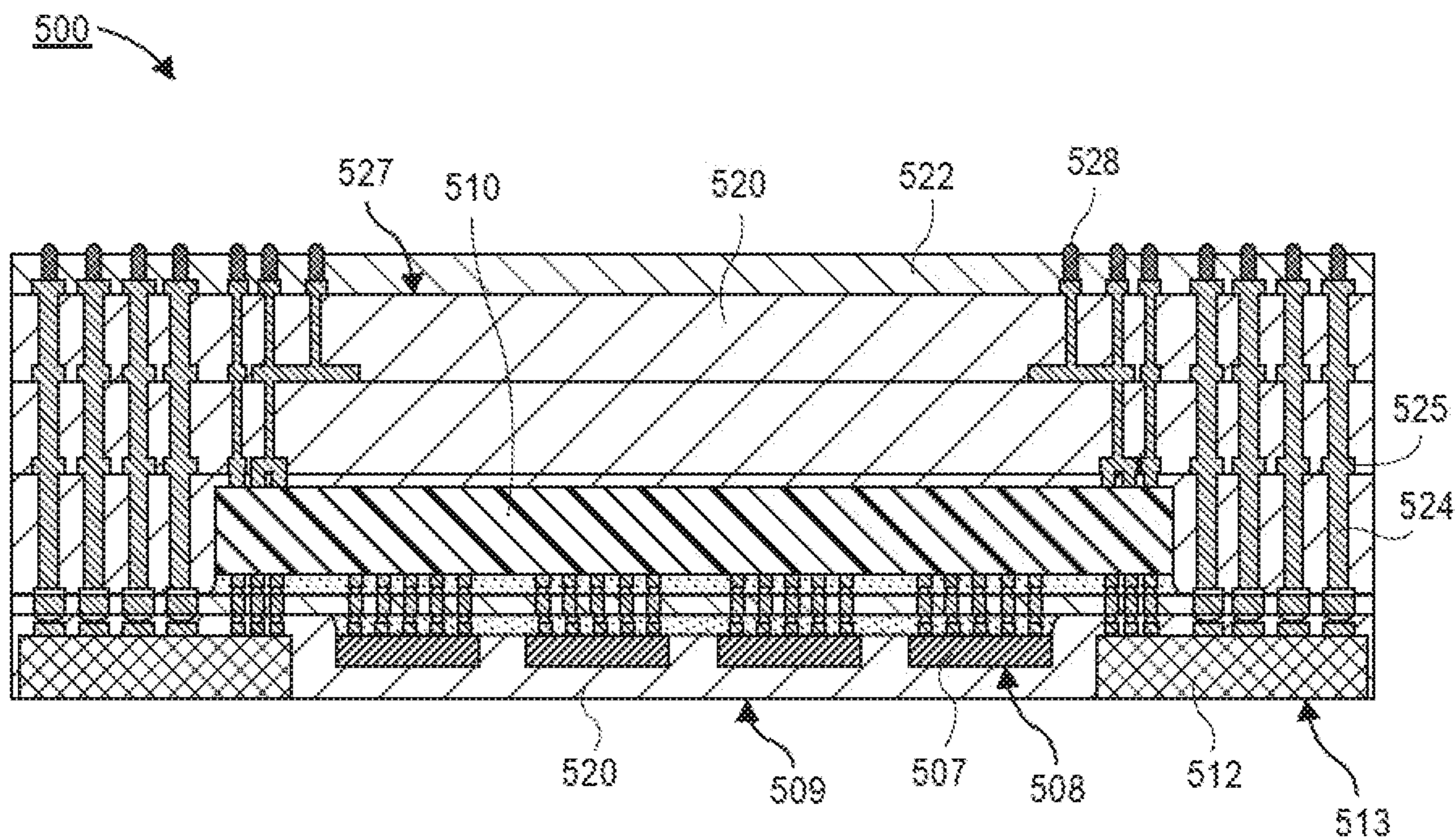


FIG. 5G

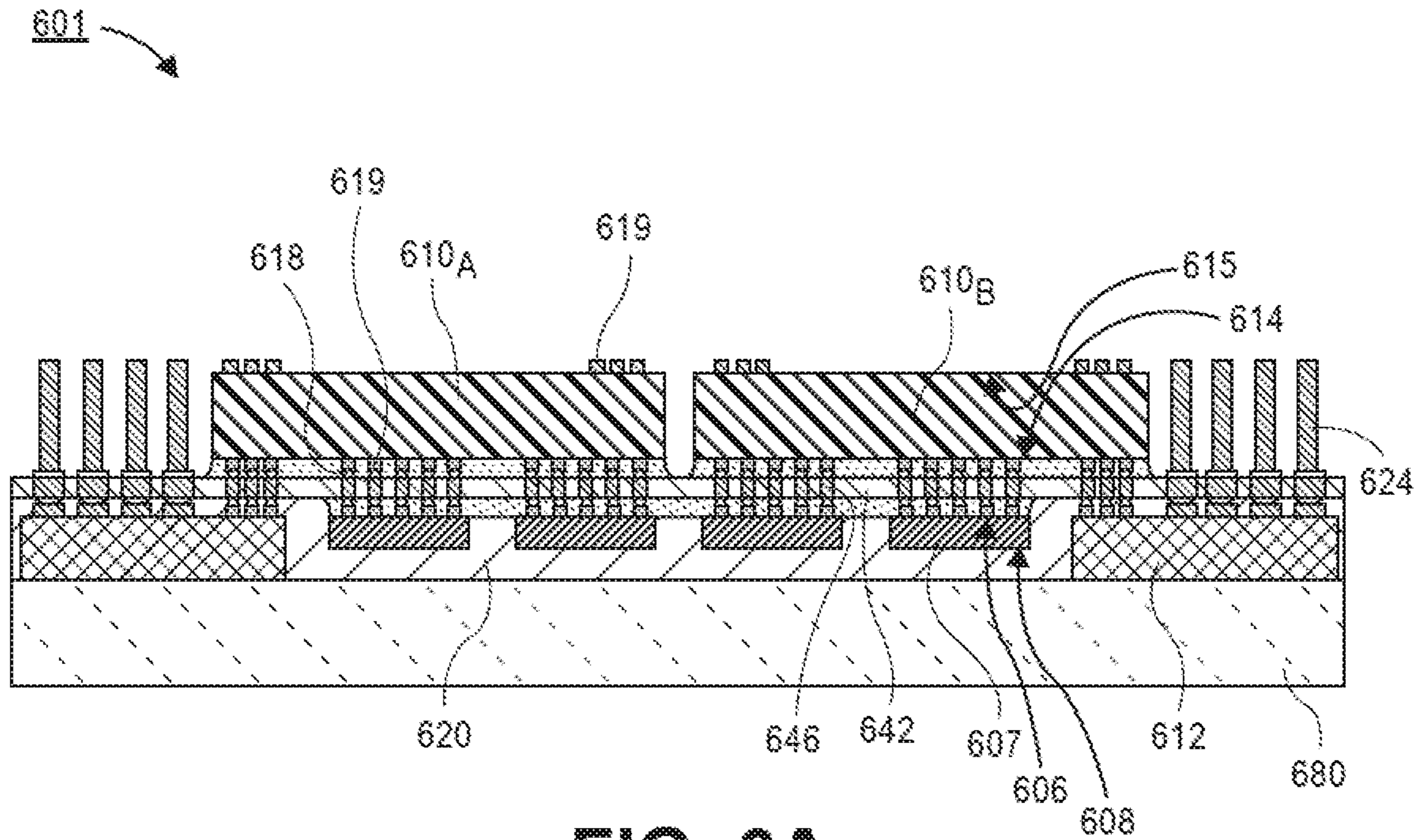


FIG. 6A

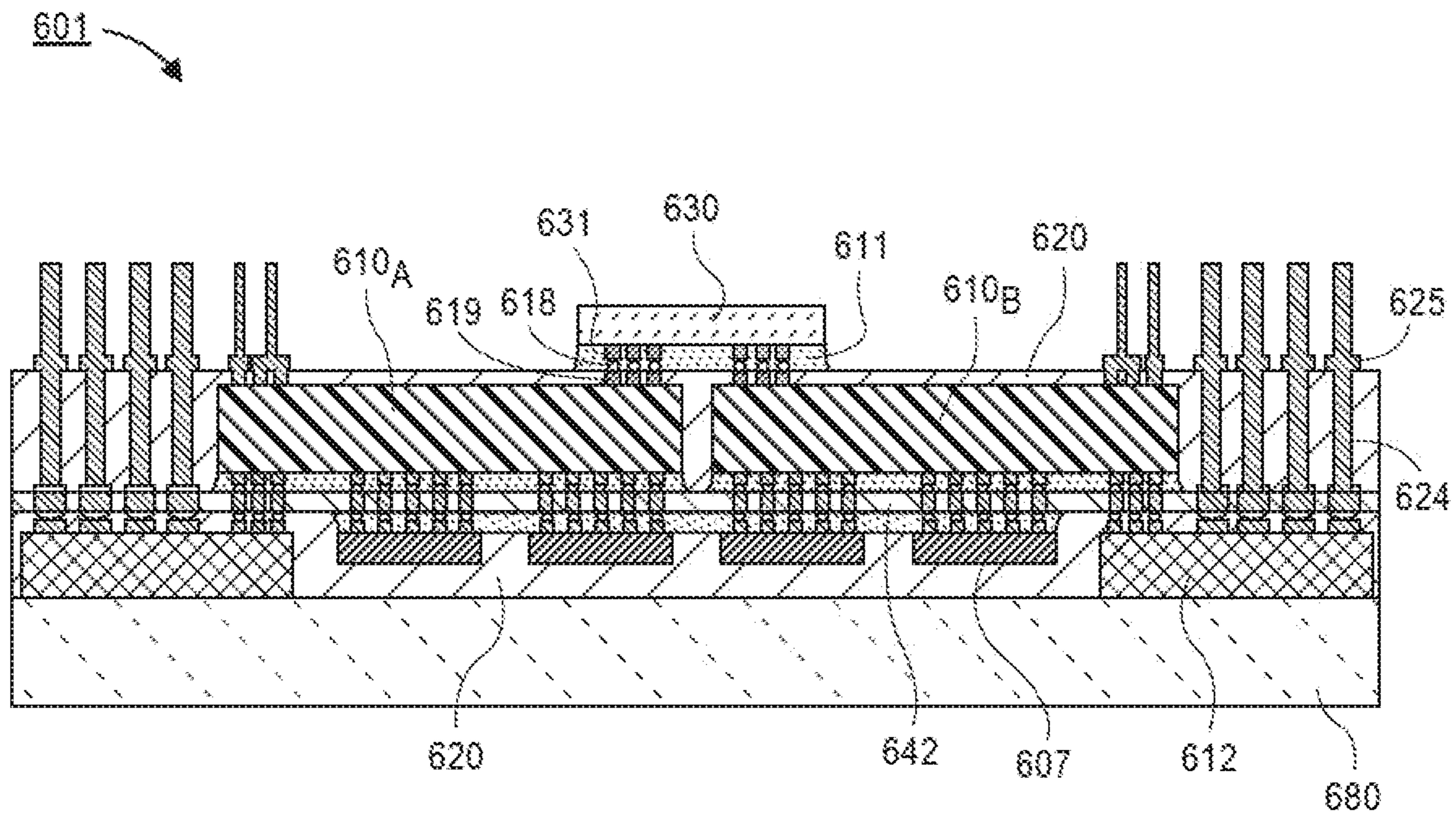


FIG. 6B

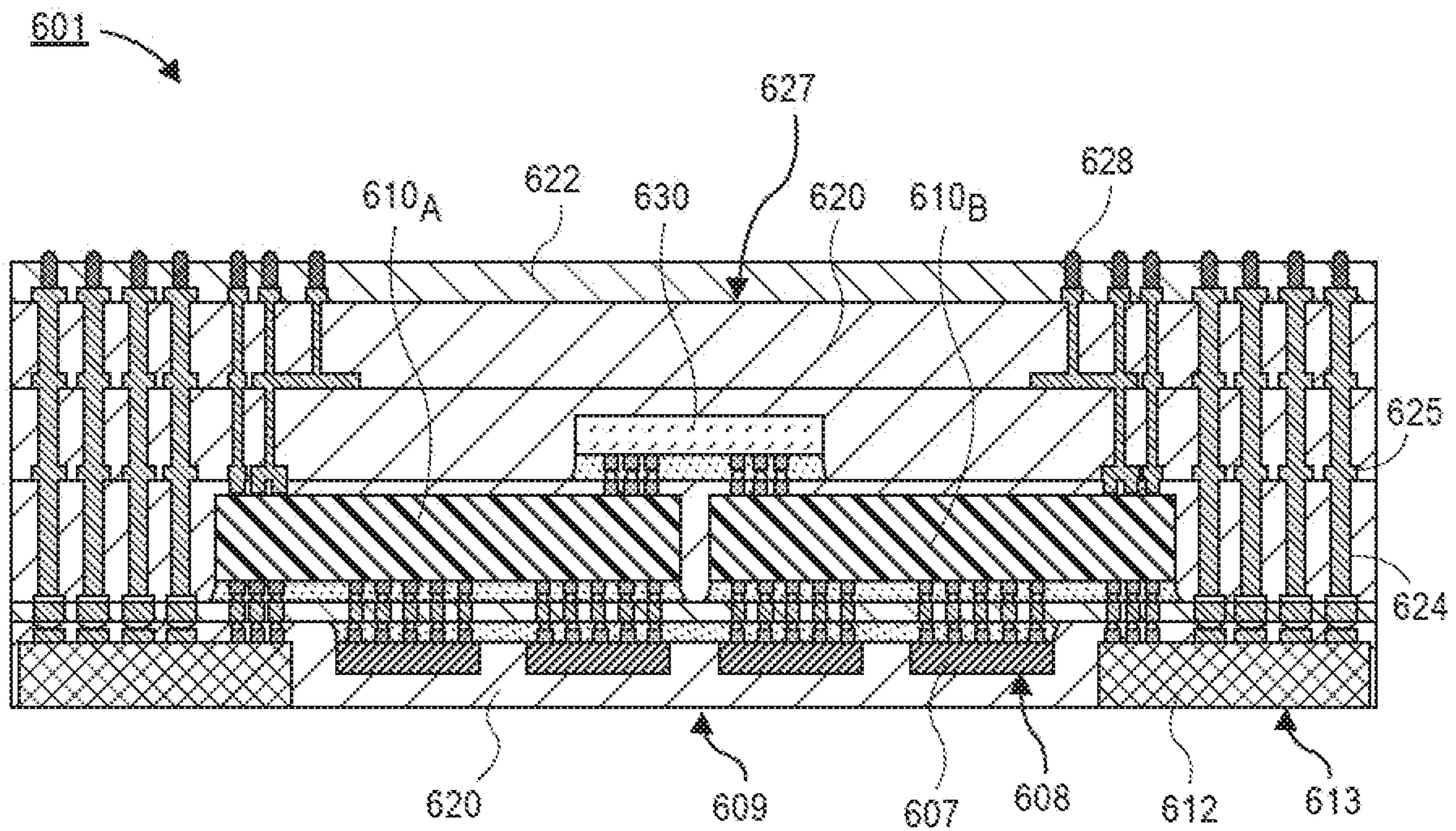


FIG. 6C

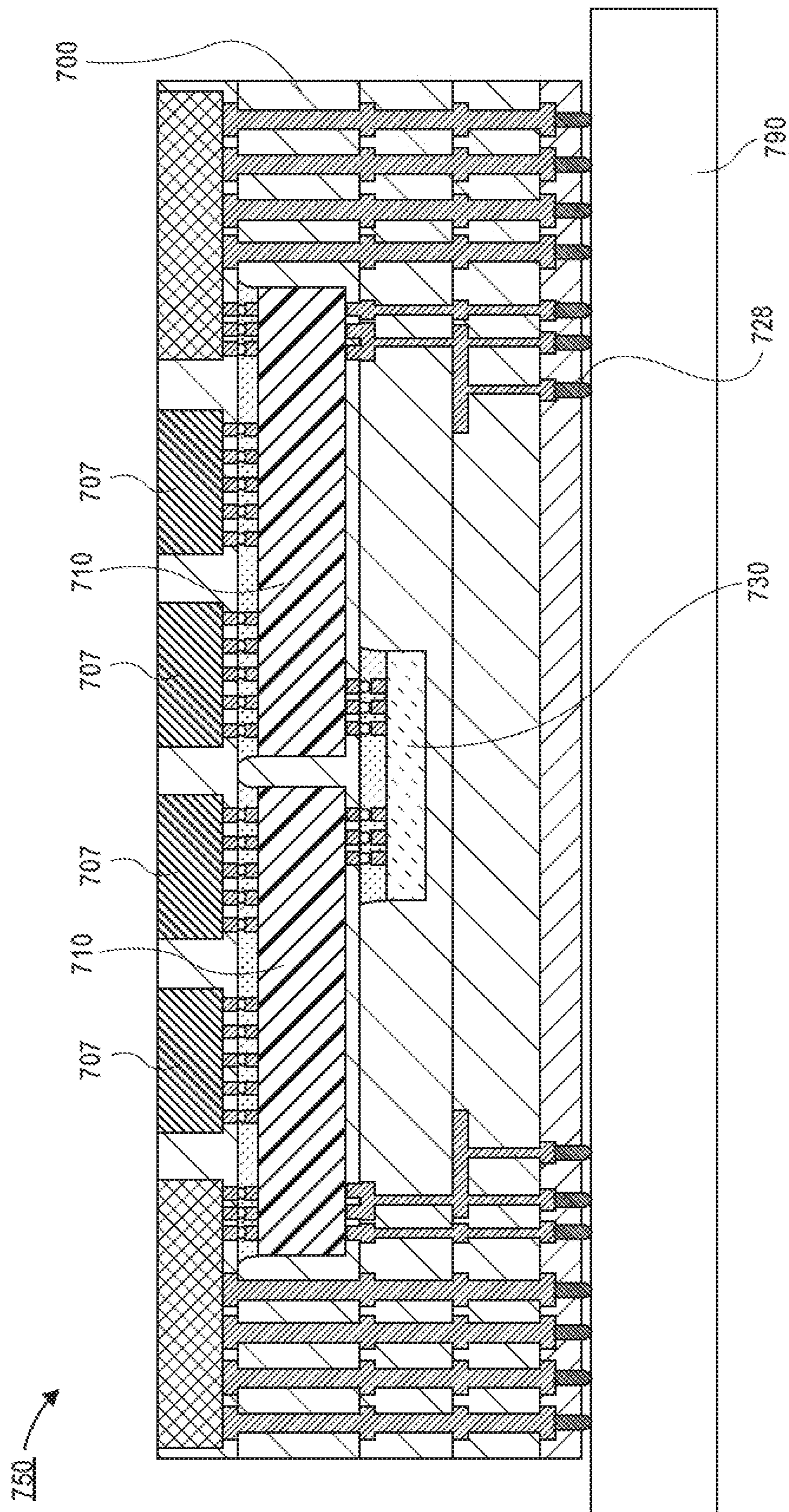


FIG. 7

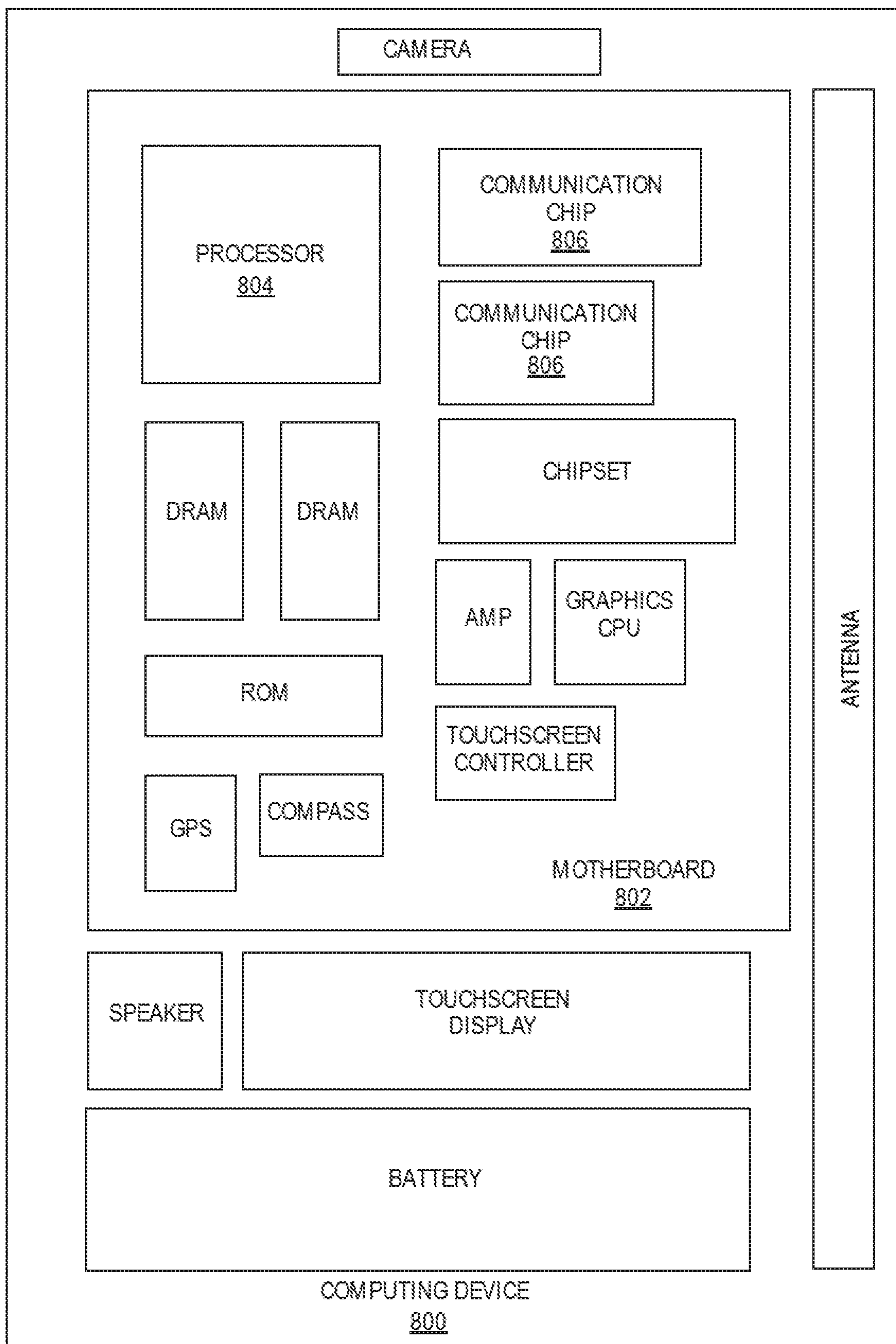


FIG. 8

CHIPLET FIRST ARCHITECTURE FOR DIE TILING APPLICATIONS

TECHNICAL FIELD

Embodiments of the present disclosure relate to electronic packaging, and more particularly, to multi-die electronic packages with first dies and a second die over the first dies and methods of forming such electronic packages.

BACKGROUND

The demand for miniaturization of form factor and increased levels of integration for high performance are driving sophisticated packaging approaches in the semiconductor industry. Die partitioning enabled by embedded multi-die interconnect bridge (EMIB) architectures allows for miniaturization of small form factor and high performance without yield issues seen with other methods. However, such packaging architectures require fine die-to-die interconnects that are susceptible to yield issues due to poor bump thickness variation (BTV) (e.g., due to warpage, limitations on assembly tools, and the like).

Alternative approaches using a patch containing a coarse node die between the fine dies and traditional organic substrates have been proposed as well. Such architectures allow for the integration of dies that are formed at different process nodes. This architecture also has several limitations as well. Particularly, the advanced node dies are attached to the lower node die at later stages of the package formation using thermal compression bonding (TCB). Accordingly, die placement accuracy is limited by the TCB toolset and by warpage. The TCB attach in later stages imposes stringent warpage limitations on the patch and drives a significantly lower TCB window. Furthermore, architecture proposed also relies on a second carrier attach after the advanced node dies are attached in order to implement mid-level interconnect (MLI) and Package Side Bumps (PSB). This leads to additional yield losses.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1A is a cross-sectional illustration of a multi-die package that includes a plurality of first dies coupled to a second die in a face-to-face configuration, in accordance with an embodiment.

FIG. 1B is a cross-sectional illustration of a multi-die package that includes a plurality of first dies coupled to a plurality of second dies in a face-to-face configuration, where the second dies are coupled together by an embedded bridge, in accordance with an embodiment.

FIG. 2A is a cross-sectional illustration of a multi-die package that includes a plurality of first dies coupled to a second die with a solder resist layer between the first dies and the second die, in accordance with an embodiment.

FIG. 2B is a cross-sectional illustration of a multi-die package that includes a plurality of first dies coupled to a plurality of second dies with a solder resist layer between the first dies and the second dies, where the second dies are coupled together by an embedded bridge, in accordance with an embodiment.

FIG. 3A is a cross-sectional illustration of a plurality of first dies mounted to a carrier substrate, in accordance with an embodiment.

FIG. 3B is a cross-sectional illustration after a mold layer is disposed over the plurality of first dies, in accordance with an embodiment.

FIG. 3C is a cross-sectional illustration after pillars are formed over the mold layer, in accordance with an embodiment.

FIG. 3D is a cross-sectional illustration after a second die is attached to the first dies, in accordance with an embodiment.

FIG. 3E is a cross-sectional illustration after a mold layer is disposed over the second die, in accordance with an embodiment.

FIG. 3F is a cross-sectional illustration after pillars are formed over the mold layer, in accordance with an embodiment.

FIG. 3G is a cross-sectional illustration after a redistribution layer (RDL) is formed over the mold layer, in accordance with an embodiment.

FIG. 3H is a cross-sectional illustration after a solder resist layer is disposed over the RDL and patterned, in accordance with an embodiment.

FIG. 3I is a cross-sectional illustration after mid-level interconnects (MLIs) are disposed through the solder resist layer, in accordance with an embodiment.

FIG. 3J is a cross-sectional illustration after the carrier is removed, in accordance with an embodiment.

FIG. 4A is a cross-sectional illustration of an electronic package after a plurality of second dies are attached to a plurality of first dies, in accordance with an embodiment.

FIG. 4B is a cross-sectional illustration after a mold layer is disposed over the second dies, in accordance with an embodiment.

FIG. 4C is a cross-sectional illustration after a bridge is attached across the second dies, in accordance with an embodiment.

FIG. 4D is a cross-sectional illustration after mold layers and RDLs are formed over the second dies, in accordance with an embodiment.

FIG. 4E is a cross-sectional illustration after the carrier is removed, in accordance with an embodiment.

FIG. 5A is a cross-sectional illustration of a first carrier with a seed layer, in accordance with an embodiment.

FIG. 5B is a cross-sectional illustration after a solder resist layer is disposed over the seed layer and patterned, in accordance with an embodiment.

FIG. 5C is a cross-sectional illustration after interconnects are disposed into the solder resist openings, in accordance with an embodiment.

FIG. 5D is a cross-sectional illustration after first dies are attached to the interconnects, in accordance with an embodiment.

FIG. 5E is a cross-sectional illustration after the first carrier is removed and a second carrier is attached to the package, in accordance with an embodiment.

FIG. 5F is a cross-sectional illustration after a second die is attached to the first dies, in accordance with an embodiment.

FIG. 5G is a cross-sectional illustration after RDLs are formed over the second die and the second carrier is removed, in accordance with an embodiment.

FIG. 6A is a cross-sectional illustration of a package with a plurality of second dies attached to the first dies, in accordance with an embodiment.

FIG. 6B is a cross-sectional illustration after a bridge is attached across the second dies, in accordance with an embodiment.

FIG. 6C is a cross-sectional illustration after RDLs are formed over the second dies and the second carrier is removed, in accordance with an embodiment.

FIG. 7 is a cross-sectional illustration of an electronic system that comprises a multi-chip package, in accordance with an embodiment.

FIG. 8 is a schematic of a computing device built in accordance with an embodiment.

EMBODIMENTS OF THE PRESENT DISCLOSURE

Described herein are multi-die electronic packages with first dies and a second die over the first dies and methods of forming such electronic packages, in accordance with various embodiments. In the following description, various aspects of the illustrative implementations will be described using terms commonly employed by those skilled in the art to convey the substance of their work to others skilled in the art. However, it will be apparent to those skilled in the art that the present invention may be practiced with only some of the described aspects. For purposes of explanation, specific numbers, materials and configurations are set forth in order to provide a thorough understanding of the illustrative implementations. However, it will be apparent to one skilled in the art that the present invention may be practiced without the specific details. In other instances, well-known features are omitted or simplified in order not to obscure the illustrative implementations.

Various operations will be described as multiple discrete operations, in turn, in a manner that is most helpful in understanding the present invention, however, the order of description should not be construed to imply that these operations are necessarily order dependent. In particular, these operations need not be performed in the order of presentation.

As noted above, multi-die packages provide the ability to continue scaling to smaller form factors while also obtaining advanced performance. However, current architectures suffer from assembly issues that negatively impact yield. Accordingly, embodiments disclosed herein include multi-die packages that are assembled with a process flow that minimizes warpage and alignment issues.

Particularly, embodiments disclosed herein include a plurality of first dies that are at an advanced process node and one or more second dies at a lower process node. In an embodiment, the first dies are placed into the package at the initial stages of package assembly. The early placing of the first dies has several advantages. For one, the placement process may be implemented with a die mounter instead of a thermal compression bonding (TCB) tool. Die mounters have a placement accuracy that is an order of magnitude accurate than a TCB tool. Additionally, there is less warpage during early stage placement of the first dies.

In an embodiment, the attachment of the lower node second die to the first dies also has a larger TCB window. The TCB window is improved since the package is still attached to the first dies on a dimensionally stable (e.g., glass) carrier in place which results in low warpage. Additionally, embodiments allow for mid-level interconnects (MLI) and PSB formation before the carrier is removed. Accordingly, additional carriers otherwise needed for the formation of such features is avoided.

Referring now to FIG. 1A, a cross-sectional illustration of a multi-die electronic package 100 is shown, in accordance with an embodiment. In an embodiment, the electronic package 100 may comprise a mold layer 120 with a plurality of dies embedded in the mold layer. For example, a plurality of first dies 107 and a second die 110 may be embedded in the mold layer 120. While the mold layer 120 is shown as

being comprised of discrete layers, it is to be appreciated that no discernable boundary may be present between the different portions of the mold layer 120. In an embodiment, the mold layer 120 may comprise a first surface 109 and a second surface 127 opposite from the first surface 109. The mold layer 120 may comprise any suitable material for electronic packaging, such as epoxy or the like.

In an embodiment, a plurality of first dies 107 may be embedded in the mold layer 120 such that a surface 108 of the first dies 107 is substantially coplanar with the first surface 109 of the mold layer 120. In an embodiment, the surface 108 may be referred to as a backside surface of the first dies 107. Since the backside surface 108 is exposed, thermal management of the electronic package 100 is improved. In some embodiments, a heat sink or other thermal solution may be attached to the backside surface 108 of the first dies 107.

In an embodiment, a plurality of high speed input/output HSIO dies 112 may also be embedded in the mold layer 120. The HSIO dies 112 may be substantially coplanar with the first dies 107. That is, a backside surface 113 of the HSIO dies 112 may be substantially coplanar with the first surface 109 of the mold layer 120 and the backside surface 108 of the first dies 107.

In an embodiment, the plurality of first dies 107 may be electrically coupled to a second die 110 that is embedded in the mold layer 120. In an embodiment, the second die 110 is positioned between an active surface 106 of the first dies 107 and the second surface 127 of the mold layer 120. The second die 110 may have an active surface 114 and a backside surface 115. In an embodiment, the second die 110 and the first dies 107 are arranged in a face-to-face configuration. That is, the active surface 114 of the second die 110 faces the active surfaces 106 of the first dies 107. In an embodiment, the first dies 107 may be fabricated at a first process node and the second die 110 may be fabricated at a second process node that is less advanced than the first process node.

In an embodiment, the first dies 107 may be electrically coupled to the second die 110 with first level interconnects (FLIs) 118. For example, pads 117 of the first dies 107 may be electrically coupled to pads 119 of the second die 110 by FLIs 118, such as controlled collapse chip connection (C4) bumps, or the like. In an embodiment, the pads 119 of the second die 110 and the FLIs 118 may be surrounded by an underfill material 111, and the pads 117 of the first die 107 may be surrounded by the mold layer 120.

In a particular embodiment, the first dies 107 may be interconnected to each other through the second die 110. That is, the second die 110 may function as a patch to provide interconnections between each of the first dies 107. In some embodiments, the first dies 107 may all be substantially similar to each other. In other embodiments, the first dies 107 may comprise different functionalities. In the illustrated embodiment, four first dies 107 are shown. However, it is to be appreciated that an array of any number of first dies 107 (e.g., two or more) may be used in an electronic package 100.

In an embodiment, the HSIO dies 112 may also be electrically coupled to the second die 110. For example, the HSIO dies 112 may be electrically coupled to pads 119 on the second die 110 by FLIs 118 in substantially the same manner the first dies 107 are connected to the second die 110. In an embodiment, the second die 110 may provide interconnections between the first dies 107 and the HSIO dies 112.

In an embodiment, a plurality of redistribution layers (RDLs) comprising conductive traces, pads **125**, and vias **124** may be embedded in the mold layer **120**. The RDLs may electrically couple surfaces of the first dies **107**, the second die **110**, and the HSIO dies **112** to mid-level interconnects (MLIs) **128** over the second surface **127** of the mold layer **120**. In an embodiment, the MLIs **128** may be positioned in openings through a solder resist **122**, as is known in the art.

Referring now to FIG. **1B**, a cross-sectional illustration of an electronic package **101** is shown, in accordance with an additional embodiment. In an embodiment, the electronic package **101** may be substantially similar to the electronic package **100** described above with respect to FIG. **1A**, with the exception that a plurality of second dies **110** are included. In the illustrated embodiment, two second dies **110A** and **110E** are shown. However, it is to be appreciated that an array of any number of second dies **110** (e.g., two or more) may be included in electronic package **101**.

In an embodiment, the second dies **110** may be electrically coupled together with one or more bridges **130**. The bridge **130** may be an embedded multi-die interconnect bridge (EMIB) or the like. For example, the bridge **130** may include pads **131** with fine pitch that is suitable for connecting to pads **119** on the backside surface **115** of the second dies **110**. For example, FLIs **118** may electrically couple pads **131** to pads **119**. In an embodiment, the pads **131** and FLIs **118** may be surrounded by an underfill material **111**, and the pads **119** on the backside surface **115** of the second dies **110** may be surrounded by the mold layer **120**.

The interconnection of an array of second dies **110** with one or more bridges **130** provides a die tiling architecture. That is, the plurality of second dies **110** may function as a single die. This may be particularly beneficial when the combined area of the second dies exceeds the reticle limit of the process node used to fabricate the second dies **110**.

Referring now to FIG. **2A**, a cross-sectional illustration of an electronic package **200** is shown, in accordance with an embodiment. In an embodiment, the electronic package **200** may comprise a mold layer **220** with a plurality of dies embedded in the mold layer. For example, a plurality of first dies **207** and a second die **210** may be embedded in the mold layer **220**. While the mold layer **220** is shown as being comprised of discrete layers, it is to be appreciated that no discernable boundary may be present between the different portions of the mold layer **220**. In an embodiment, the mold layer **220** may comprise a first surface **209** and a second surface **227** opposite from the first surface **209**. The mold layer **220** may comprise any suitable material for electronic packaging, such as epoxy or the like.

In an embodiment, a plurality of first dies **207** may be embedded in the mold layer **220**. In contrast to the electronic package **100** described above, a surface **208** of the first dies **207** may be covered by the mold layer **220**. In an embodiment, the surface **208** may be referred to as a backside surface of the first dies **207**.

In an embodiment, a plurality of HSIO dies **212** may also be embedded in the mold layer **220**. The HSIO dies **212** may be substantially coplanar with the first surface **209** of the mold layer **220**. That is, a backside surface **213** of the HSIO dies **212** may be substantially coplanar with the first surface **209** of the mold layer **220**. In an embodiment, a thickness T_1 of the first dies **207** may be different than a thickness T_2 of the HSIO dies **212**. For example, the thickness T_1 of the first dies **207** may be less than the thickness T_2 of the HSIO dies **212**. As shown in FIG. **2A**, the backside surfaces **213** of HSIO dies **212** are substantially coplanar with the surface **209** of mold layer **220**. However, it is to be appreciated that

the mold layer **220** may also completely embed the HSIO dies **212** so that backside surface **213** is covered by the mold layer **220**.

In an embodiment, the plurality of first dies **207** may be electrically coupled to a second die **210** that is embedded in the mold layer **220**. In an embodiment, the second die **210** is positioned between an active surface **206** of the first dies **207** and the second surface **227** of the mold layer **220**. The second die **210** may have an active surface **214** and a backside surface **215**. In an embodiment, the second die **210** and the first dies **207** are arranged in a face-to-face configuration. That is, the active surface **214** of the second die **210** faces the active surfaces **206** of the first dies **207**. In an embodiment, the first dies **207** may be fabricated at a first process node and the second die **210** may be fabricated at a second process node that is less advanced than the first process node. In an embodiment, a solder resist layer **242** may be located between the first dies **207** and the second die **210**.

In an embodiment, the first dies **207** may be electrically coupled to the second die **210** with first level interconnects (FLIs) **218** and a via **246** through the solder resist layer **242**. For example, pads **217** of the first dies **207** may be electrically coupled to the vias **246** by FLIs **218**. The opposite surface of the vias **246** may be electrically coupled to pads **219** of the second die **210** by FLIs **218** as well. In an embodiment, the pads **219** of the second die **210** and the FLIs **218** between the vias **246** and the second die **210** may be surrounded by an underfill material **211**. In an embodiment, the pads **217** of the first die **207** and the FLIs **218** between the first dies **207** may be surrounded by a different underfill material **211**.

In a particular embodiment, the first dies **207** may be interconnected to each other through the second die **210**. That is, the second die **210** may function as a patch to provide interconnections between each of the first dies **207**. In some embodiments, the first dies **207** may all be substantially similar to each other. In other embodiments, the first dies **207** may comprise different functionalities. In the illustrated embodiment, four first dies **207** are shown. However, it is to be appreciated that an array of any number of first dies **207** (e.g., two or more) may be used in an electronic package **200**.

In an embodiment, the HSIO dies **212** may also be electrically coupled to the second die **210**. For example, the HSIO dies **212** may be electrically coupled to pads **219** on the second die **210** by FLIs **218** and vias **246** through the solder resist layer **242** in substantially the same manner the first dies **207** are connected to the second die **210**. In an embodiment, the second die **210** may provide interconnections between the first dies **207** and the HSIO dies **212**.

In an embodiment, a plurality of redistribution layers (RDLs) comprising conductive traces, pads **225**, and vias **224** may be embedded in the mold layer **220**. The RDLs may electrically couple surfaces of the first dies **207**, the second die **210**, and the HSIO dies **212** to mid-level interconnects (MLIs) **228** over the second surface **227** of the mold layer **220**. In an embodiment, the MLIs **228** may be positioned in openings through a solder resist **222**, as is known in the art.

Referring now to FIG. **2B**, a cross-sectional illustration of an electronic package **201** is shown, in accordance with an additional embodiment. In an embodiment, the electronic package **201** may be substantially similar to the electronic package **200** described above with respect to FIG. **2A**, with the exception that a plurality of second dies **210** are included. In the illustrated embodiment, two second dies **210A** and **210E** are shown. However, it is to be appreciated

that an array of any number of second dies **210** (e.g., two or more) may be included in electronic package **201**.

In an embodiment, the second dies **210** may be electrically coupled together with one or more bridges **230**. The bridge **230** may be an EMIB or the like. For example, the bridge **230** may include pads **231** with fine pitch that is suitable for connecting to pads **219** on the backside surface **215** of the second dies **210**. For example, FLIs **218** may electrically couple pads **231** to pads **219**. In an embodiment, the pads **231** and FLIs **218** may be surrounded by an underfill material **211**, and the pads **219** on the backside surface **215** of the second dies **210** may be surrounded by the mold layer **220**.

The interconnection of an array of second dies **210** with one or more bridges **230** provides a die tiling architecture. That is, the plurality of second dies **210** may function as a single die. This may be particularly beneficial when the combined area of the second dies exceeds the reticle limit of the process node used to fabricate the second dies **210**.

Referring now to FIGS. 3A-3J, a series of cross-sectional illustrations depicting a process for fabricating an electronic package **300** similar to the electronic package **100** described in FIG. 1A is shown, in accordance with an embodiment. As will be apparent, the process includes mounting the first dies **307** early in the assembly process in order to provide improved alignment that is not susceptible to variations arising from warpage.

Referring now to FIG. 3A, a cross-sectional illustration of an electronic package **300** after placement of the first dies **307** is shown, in accordance with an embodiment. In an embodiment, the first dies **307** may be attached to a release layer **371** over a carrier **370**. The carrier **370** may be a dimensionally stable material that is not susceptible to significant warpings. For example, the carrier **370** may be a glass carrier.

In an embodiment, the first dies **307** may be mounted to the release layer with a die mounter tool. The use of a die mounter tool to place the first dies **307** provides improved placement accuracy compared to TCB tools. A die mounter tool typically has a placement precision that is an order of magnitude better than TCB tools. For example, a TCB tool typically has a precision of $\pm 15 \mu\text{m}$ whereas a die mounter tool has a precision of $\pm 5 \mu\text{m}$.

In an embodiment, the first dies **307** are mounted to the release layer **371** with a backside surface **308** interfacing with the release layer **371**. Accordingly, an active surface **306** and pads **317** on the active surface **306** of the first dies **307** are facing away from the carrier **370**. In an embodiment, a plurality of HSIO dies **312** may also be mounted to the release layer **371**. A backside surface **313** of the HSIO dies **312** may interface with the release layer **371** with pads **317** facing away from the carrier **370**. Accordingly, the backside surfaces **308** of the first dies **307** may be substantially coplanar with backside surfaces **313** of the HSIO dies **312**.

Referring now to FIG. 3B, a cross-sectional illustration of the electronic package **300** after a mold layer **320** is disposed over the first dies **307**, the HSIO dies **312** and the carrier **370** is shown, in accordance with an embodiment. In an embodiment, the mold layer **320** may be disposed and planarized in order to expose surfaces of the pads **317** of the first dies **307** and the HSIO dies **312**. The mold layer **320** may be planarized with a grinding or polishing process, as is known in the art.

Referring now FIG. 3C, a cross-sectional illustration of the electronic package **300** after vias **324** are fabricated over selected pads **317** is shown, in accordance with an embodiment. In an embodiment, the vias **324** may be conductive

pillars or any other suitable conductive feature for forming vias in an electronic package. In an embodiment, the vias **324** may be fabricated over pads **317** on the HSIO dies **312**.

Referring now to FIG. 3D, a cross-sectional illustration of the electronic package after a second die **310** is attached to the first dies **307** and the HSIO dies **312** is shown, in accordance with an embodiment. In an embodiment, the second die **310** may be attached with a TCB tool. Since the TCB attach happens in the early stages of package assembly (and with the dimensionally stable carrier **370** still in place) the impact of warpage is minimal. Accordingly, yield loss is minimal or none.

In an embodiment, the second die **310** may be coupled to the first dies **307** and the HSIO dies **312** with FLIs **318**. For example, C4 bumps may electrically couple pads **317** of the first dies **307** and the HSIO dies **312** to pads **319** of the second die **310**. In an embodiment, an underfill material **311** may surround the FLIs **318** and the pads **319** of the second die **310**.

In an embodiment, the second die **310** may be mounted to the first dies **307** in a face-to-face configuration. That is, an active surface **314** of the second die **310** may face the active surface **306** (i.e., the surface below pads **317**) of the first dies **307**. In an embodiment, pads **319** may also be formed over a backside surface **315** of the second die **310**. The pads **319** over the backside surface **315** may be pads for through substrate vias (TSVs) (not shown) that allow for electrical connections to pass through the second die **310** from the active surface **314** to the backside surface **315**. In an embodiment, the first dies **307** may be fabricated at a first process node and the second die **310** may be fabricated at a second process node that is less advanced than the first process node.

Referring now to FIG. 3E, a cross-sectional illustration of the electronic package **300** after a mold layer **320** is disposed over and around the second die **310** and the vias **324** is shown, in accordance with an embodiment. In an embodiment, the mold layer **320** may be planarized (e.g., with polishing or grinding) to expose surfaces of the pads **319** and the vias **324**.

Referring now to FIG. 3F, a cross-sectional illustration of the electronic package **300** after pads **325** and vias **324** are formed is shown, in accordance with an embodiment. In an embodiment, the pads **325** and the vias **324** may be for a redistribution layer (RDL) formed above the second die **310**.

Referring now to FIG. 3G, a cross-sectional illustration of the electronic package **300** after additional RDLs are formed is shown, in accordance with an embodiment. In an embodiment, the RDLs may comprise pads **325** and vias **324** embedded in a mold layer **320**. In an embodiment, the RDLs are fabricated with a lithographic via process (e.g., pad/via formation, molding, mold grinding/polishing to expose the vias, etc.). In other embodiments, the RDLs may be fabricated with a suitable semi-additive process (SAP) using traditional High Density Interconnect (HDI) organic build-up dielectric layers, plating, and the like. As shown in FIG. 3G, the mold layer **320** includes a plurality of distinguishable layers. However, it is to be appreciated that in some embodiments there may be no discernable boundary between layers of the mold layer **320**.

Referring now to FIG. 3H, a cross-sectional illustration of the electronic package **300** after a solder resist layer **322** is disposed over a surface **327** of the mold layer **320** and patterned is shown, in accordance with an embodiment. In an embodiment, the resist layer is patterned to form a plurality of openings **323** that expose pads **325** over the mold layer **320**.

Referring now to FIG. 3I, a cross-sectional illustration of the electronic package 300 after MLIs 328 are disposed in the openings 323 is shown, in accordance with an embodiment. In an embodiment, the MLIs 328 may comprise a solder or the like. Furthermore, it is to be appreciated that the MIL formation is implemented while the dimensionally stable carrier is still attached to the electronic package 300. Accordingly, the attachment of an additional carrier is not needed, as is the case with previously disclosed approaches.

Referring now to FIG. 3J, a cross-sectional illustration of the electronic package 300 after the carrier 370 and the release layer 371 are removed is shown, in accordance with an embodiment. In an embodiment, any release layer residue may be removed with typical wet or dry cleaning methods, as is known in the art. After cleaning, the package 300 may be singulated to have the desired size.

As shown in FIG. 3J, backside surfaces 308 of the first dies 307 are exposed. Accordingly, thermal management of the electronic package 300 is improved. In some embodiments, a thermal solution (e.g., a heat sink, a heat spreader, etc.) may be coupled to the backside surfaces 308 of the first dies 307. In an embodiment, the backside surfaces 308 of the first dies 307 may be substantially coplanar with the backside surfaces 313 of the HSIO dies 312 and the surface 309 of the mold layer 320.

Referring now to FIGS. 4A-4D, a series of cross-sectional illustrations depicting a process of forming an electronic package 401 similar to the electronic package 101 described with respect to FIG. 1B is shown, in accordance with an embodiment.

Referring now to FIG. 4A, a cross-sectional illustration of an electronic package 401 after a plurality of second dies 410 are attached to first dies is shown, in accordance with an embodiment. In an embodiment, the incoming electronic package 401 may be fabricated with substantially similar processing operations described with respect to FIGS. 3A-3C. For example, the backside surfaces 408 of first dies 407 and backside surfaces 413 of HSIO dies 412 may be mounted to a release layer 471 over a dimensionally stable carrier 470, and vias 424 may be formed over the HSIO dies 412.

In an embodiment, the second dies 410A and 410E may be attached to the first dies 407 with a TCB tool. Since the TCB attach happens in the early stages of package assembly (and with the dimensionally stable carrier 470 still in place) the impact of warpage is minimal. Accordingly, yield loss is minimal or none.

In an embodiment, the second dies 410A and 410E may be coupled to the first dies 407 and the HSIO dies 412 with FLIs 418. For example, C4 bumps may electrically couple pads 417 of the first dies 407 and the HSIO dies 412 to pads 419 of the second dies 410. In an embodiment, an underfill material 411 may surround the FLIs 418 and the pads 419 of the second die 410.

In an embodiment, the second dies 410 may be mounted to the first dies 407 in a face-to-face configuration. That is, an active surface 414 of the second dies 410 may face the active surface 406 of the first dies 407. In an embodiment, pads 419 may also be formed over a backside surface 415 of the second die 410. The pads 419 over the backside surface 415 may be pads for through substrate vias (TSVs) (not shown) that allow for electrical connections to pass through the second die 410 from the active surface 414 to the backside surface 415. In an embodiment, the first dies 407 may be fabricated at a first process node and the second dies 410 may be fabricated at a second process node that is less advanced than the first process node.

Referring now to FIG. 4B, a cross-sectional illustration of the electronic package 401 after a mold layer 420 is disposed over and around the second die 410 and the vias 424 is shown, in accordance with an embodiment. In an embodiment, the mold layer 420 may be planarized (e.g., with polishing or grinding) to expose surfaces of the pads 419 and the vias 424.

Referring now to FIG. 4C, a cross-sectional illustration of the electronic package 401 after a bridge 430 is attached across the second dies 410A and 410E is shown, in accordance with an embodiment. In an embodiment, the bridge 430 may be an EMIB or the like that provides electrical coupling between second dies 410A and 410B. The interconnection of an array of second dies 410 with one or more bridges 430 provides a die tiling architecture. That is, the plurality of second dies 410 may function as a single die. This may be particularly beneficial when the combined area of the second dies 410 exceeds the reticle limit of the process node used to fabricate the second dies 410.

In an embodiment, the bridge 430 may comprise pads 431 that are electrically coupled to pads 419 on the backside surface 415 of the second dies 410. In an embodiment the pads 419 may be electrically coupled to pads 431 with FLIs 418. The pads 431 and the FLIs 418 may be surrounded by an underfill material 411. While a single bridge 430 is shown in FIG. 4C, it is to be appreciated that electronic package 401 may comprise a plurality of bridges 430 to provide connections between any number of second dies 410.

Referring now to FIG. 4D, a cross-sectional illustration of the electronic package after RDLs comprising pads 425, vias 424, and mold layers 420 is fabricated over the second dies 410 is shown, in accordance with an embodiment. In an embodiment, the RDLs may be fabricated with a lithographic via process or with standard SAP processes. In an embodiment, a solder resist 422 may be formed over a surface 427 of the mold layer 420. MLIs 428 may pass through the solder resist 422 to provide connections to pads 425. Furthermore, it is to be appreciated that the MIL formation is implemented while the dimensionally stable carrier is still attached to the electronic package 401. Accordingly, the attachment of an additional carrier is not needed, as is the case with previously disclosed approaches.

Referring now to FIG. 4E, a cross-sectional illustration of the electronic package 401 after the carrier 470 and the release layer 471 are removed is shown, in accordance with an embodiment. In an embodiment, any release layer residue may be removed with typical wet or dry cleaning methods, as is known in the art. After cleaning, the package 401 may be singulated to have the desired size.

As shown in FIG. 4E, backside surfaces 408 of the first dies 407 are exposed. Accordingly, thermal management of the electronic package 401 is improved. In some embodiments, a thermal solution (e.g., a heat sink, a heat spreader, etc.) may be coupled to the backside surfaces 408 of the first dies 407. In an embodiment, the backside surfaces 408 of the first dies 407 may be substantially coplanar with the backside surfaces 413 of the HSIO dies 412 and the surface 409 of the mold layer 420.

Referring now to FIGS. 5A-5G, a series of cross-sectional illustrations depicting a process to form an electronic package 500 similar to the electronic package 200 shown in FIG. 2A is shown, in accordance with an embodiment.

Referring now to FIG. 5A, a cross-sectional illustration of a first carrier 570 with a seed layer 573 is shown, in accordance with an embodiment. In an embodiment, the first carrier 570 may be any dimensionally stable carrier, such as glass.

11

Referring now to FIG. 5B, a cross-sectional illustration of the electronic package 500 after a solder resist layer 542 with patterned openings 543 is disposed over the seed layer 573 is shown, in accordance with an embodiment. The solder resist layer 542 may be disposed with a lamination process, or the like.

Referring now to FIG. 5C, a cross-sectional illustration of the electronic package 500 after vias 546 and FLIs 518 are disposed in the openings 543 is shown, in accordance with an embodiment. In an embodiment, the vias 546 may be copper or the like, and the FLIs 518 may be solder bumps or the like.

Referring now to FIG. 5D, a cross-sectional illustration of the electronic package 500 after first dies 507 and HSIO dies 512 are mounted is shown, in accordance with an embodiment. In an embodiment, the first dies 507 and the HSIO dies 512 may be mounted to FLIs 518 with a TCB tool. Accordingly, pads 517 may be attached to the FLIs 518. The pads 517 and FLIs 518 may be surrounded by an underfill material 511. As shown, the first dies 507 may be attached with a face down configuration. That is, active surfaces 506 of the first dies 507 may face towards the first carrier 570 and backside surfaces 508 of the first dies 507 may face away from the first carrier 570.

In an embodiment, the face down configuration provides an advantage in that thicknesses of the first dies 507 and the HSIO dies 512 need not be the same. For example, first dies 507 may have a first thickness T_1 and HSIO dies 512 may have a second thickness T_2 that is different (e.g., greater) than the first thickness T_1 . In an embodiment, a mold layer 520 may be disposed over and around the first dies 507 and the HSIO dies 512 after they have been mounted to the first carrier 570. In some embodiments, the molded layer 520 may be recessed with a grinding or polishing process to expose the HSIO die back surface.

Referring now to FIG. 5E, a cross-sectional illustration of the electronic package 500 after the first carrier 570 is removed and a second carrier 580 is attached to an opposing surface of the electronic package 500. As shown, the second carrier 580 may interface with the mold layer 520 and the solder resist 542 is now facing upwards away from the second carrier 580. In an embodiment, the seed layer 573 may be patterned to form pads 574 over the vias 546.

Referring now to FIG. 5F, a cross-sectional illustration of the electronic package 500 after vias 524 are fabricated and a second die 510 is attached to the first dies 507 and the HSIO dies 512 is shown, in accordance with an embodiment. In an embodiment, the second die 510 may be attached with a TCB tool. Since the TCB attach happens in the early stages of package assembly (and with the dimensionally stable second carrier 580 still in place) the impact of warpage is minimal. Accordingly, yield loss is minimal or none.

In an embodiment, the second die 510 may be coupled to the first dies 507 and the HSIO dies 512 with FLIs 518. For example, FLIs 518 may couple pads 519 of the second die 510 to the vias 546 through the solder resist 542. In an embodiment, an underfill material 511 may surround the FLIs 518 and the pads 519 of the second die 510.

In an embodiment, the second die 510 may be mounted to the first dies 507 in a face-to-face configuration. That is, an active surface 514 of the second die 510 may face the active surface 506 of the first dies 507. In an embodiment, pads 519 may also be formed over a backside surface 515 of the second die 510. The pads 519 over the backside surface 519 may be pads for through substrate vias (TSVs) (not shown) that allow for electrical connections to pass through the

12

second die 510 from the active surface 514 to the backside surface 515. In an embodiment, the first dies 507 may be fabricated at a first process node and the second die 510 may be fabricated at a second process node that is less advanced than the first process node.

Referring now to FIG. 5G, a cross-sectional illustration after RDLs comprising pads 525 and vias 524 are formed and the second carrier 580 is removed is shown, in accordance with an embodiment. In an embodiment, the RDLs are fabricated with a lithographic via process or a SAP process, as is known in the art. As shown in FIG. 5G, the mold layer 520 includes a plurality of distinguishable layers. However, it is to be appreciated that in some embodiments there may be no discernable boundary between layers of the mold layer 520.

In an embodiment a solder resist layer 522 is disposed over a surface 527 of the mold layer 520. In an embodiment, the resist layer is patterned and MLIs 528 may be disposed. In an embodiment, the MLIs 528 may comprise a solder or the like. Furthermore, it is to be appreciated that the MLI formation is implemented while the dimensionally stable second carrier 580 is still attached to the electronic package 500. Accordingly, the attachment of an additional carrier is not needed, as is the case with previously disclosed approaches.

In an embodiment the second carrier 580 is removed to expose a surface 509 of the mold layer 520. As shown in FIG. 5G, backside surfaces 508 of the first dies 507 are embedded in the mold layer 520. The backside surface 513 of the HSIO dies 512 are exposed in some embodiments. However, in other embodiments, the backside surface 513 of the HSIO dies 512 may also be embedded in the mold layer 520.

Referring now to FIGS. 6A-6C, a series of cross-sectional illustrations depicting a process for forming an electronic package 601 similar to the electronic package 201 described with respect to FIG. 2B is shown, in accordance with an embodiment.

Referring now to FIG. 6A, a cross-sectional illustration of an electronic package 601 after a plurality of second dies 610 are coupled to first dies 607 is shown, in accordance with an embodiment. In an embodiment, the incoming electronic package 601 may be fabricated with substantially similar processing operations described with respect to FIGS. 5A-5E. For example, the backside surfaces 608 of first dies 607 and backside surfaces 613 of HSIO dies 612 may be facing a second carrier 680, and vias 624 may be formed over the HSIO dies 612. Additionally, a solder resist 642 with vias 646 may be positioned over the first dies 607 and the HSIO dies 612.

In an embodiment, the second dies 610A and 610E may be attached to the first dies 607 with a TCB tool. Since the TCB attach happens in the early stages of package assembly (and with the dimensionally stable second carrier 680 still in place) the impact of warpage is minimal. Accordingly, yield loss is minimal or none.

In an embodiment, the second dies 610A and 610E may be coupled to the first dies 607 and the HSIO dies 612 with FLIs 618. For example, FLIs 618 may couple pads 619 of the second dies 610 to the vias 646 through the solder resist 642. In an embodiment, an underfill material 611 may surround the FLIs 618 and the pads 619 of the second die 610.

In an embodiment, the second dies 610 may be mounted to the first dies 607 in a face-to-face configuration. That is, an active surface 614 of the second dies 610 may face the active surface 606 of the first dies 607. In an embodiment,

pads **619** may also be formed over backside surfaces **615** of the second dies **610**. The pads **619** over the backside surface **619** may be pads for through substrate vias (TSVs) (not shown) that allow for electrical connections to pass through the second dies **610** from the active surface **614** to the backside surface **615**. In an embodiment, the first dies **607** may be fabricated at a first process node and the second dies **610** may be fabricated at a second process node that is less advanced than the first process node.

Referring now to FIG. **6B**, a cross-sectional illustration of the electronic package **601** after a mold layer **620** surrounds the second dies **610** and a bridge **630** is attached across the second dies **610A** and **610E** is shown, in accordance with an embodiment. In an embodiment, the bridge **630** may be an EMIB or the like that provides electrical coupling between second dies **610A** and **610B**. The interconnection of an array of second dies **610** with one or more bridges **630** provides a die tiling architecture. That is, the plurality of second dies **610** may function as a single die. This may be particularly beneficial when the combined area of the second dies **610** exceeds the reticle limit of the process node used to fabricate the second dies **610**.

In an embodiment, the bridge **630** may comprise pads **631** that are electrically coupled to pads **619** on the backside surface **615** of the second dies **610**. In an embodiment the pads **619** may be electrically coupled to pads **631** with FLIs **618**. The pads **631** and the FLIs **618** may be surrounded by an underfill material **611**. While a single bridge **630** is shown in FIG. **6B**, it is to be appreciated that electronic package **601** may comprise a plurality of bridges **630** to provide connections between any number of second dies **610**.

Referring now to FIG. **6C**, a cross-sectional illustration after RDLs comprising pads **625** and vias **624** are formed and the second carrier **680** is removed is shown, in accordance with an embodiment. In an embodiment, the RDLs are fabricated with a lithographic via process or a SAP process, as is known in the art. As shown in FIG. **6C**, the mold layer **620** includes a plurality of distinguishable layers. However, it is to be appreciated that in some embodiments there may be no discernable boundary between layers of the mold layer **620**.

In an embodiment a solder resist layer **622** is disposed over a surface **627** of the mold layer **620**. In an embodiment, the resist layer is patterned and MLIs **628** may be disposed. In an embodiment, the MLIs **628** may comprise a solder or the like. Furthermore, it is to be appreciated that the MLI formation is implemented while the dimensionally stable second carrier **680** is still attached to the electronic package **601**. Accordingly, the attachment of an additional carrier is not needed, as is the case with previously disclosed approaches.

In an embodiment the second carrier **680** is removed to expose a surface **609** of the mold layer **620**. As shown in FIG. **6C**, backside surfaces **608** of the first dies **607** are embedded in the mold layer **620**. The backside surface **613** of the HSIO dies **612** are exposed in some embodiments. However, in other embodiments, the backside surface **613** of the HSIO dies **612** may also be embedded in the mold layer **620**.

Referring now to FIG. **7**, a cross-sectional illustration of an electronic system **750** is shown, in accordance with an embodiment. In an embodiment, the electronic system **750** may comprise an electronic package **700** that comprises a plurality of dies. For example, the plurality of dies may comprise first dies **707** and second dies **710**. In an embodiment, the second dies **710** may be electrically coupled together by a bridge **730**, such as an EMIB. In some

embodiments, the first dies **707** and the second dies **710** are oriented in a face-to-face configuration. In some embodiments, the first dies **707** have are fabricated at a first process node and the second dies **710** are fabricated at a second process node that is less advanced than the first process node. In an embodiment, the electronic package **700** may be any electronic package such as those disclosed in greater detail above.

In an embodiment, the electronic package **700** may be electrically coupled to a board **790**. For example, MLIs **728** of the electronic package **700** may be electrically and mechanically coupled to pads (not shown) on the board **790**. While the MLIs **728** are illustrated as solder bumps, it is to be appreciated that the electronic package **700** may be connected to the board **790** with any suitable interconnect architecture. The board **790** may be any suitable board, such as a printed circuit board (PCB) or the like.

FIG. **8** illustrates a computing device **800** in accordance with one implementation of the invention. The computing device **800** houses a board **802**. The board **802** may include a number of components, including but not limited to a processor **804** and at least one communication chip **806**. The processor **804** is physically and electrically coupled to the board **802**. In some implementations the at least one communication chip **806** is also physically and electrically coupled to the board **802**. In further implementations, the communication chip **806** is part of the processor **804**.

These other components include, but are not limited to, volatile memory (e.g., DRAM), non-volatile memory (e.g., ROM), flash memory, a graphics processor, a digital signal processor, a crypto processor, a chipset, an antenna, a display, a touchscreen display, a touchscreen controller, a battery, an audio codec, a video codec, a power amplifier, a global positioning system (GPS) device, a compass, an accelerometer, a gyroscope, a speaker, a camera, and a mass storage device (such as hard disk drive, compact disk (CD), digital versatile disk (DVD), and so forth).

The communication chip **806** enables wireless communications for the transfer of data to and from the computing device **800**. The term “wireless” and its derivatives may be used to describe circuits, devices, systems, methods, techniques, communications channels, etc., that may communicate data through the use of modulated electromagnetic radiation through a non-solid medium. The term does not imply that the associated devices do not contain any wires, although in some embodiments they might not. The communication chip **806** may implement any of a number of wireless standards or protocols, including but not limited to Wi-Fi (IEEE 802.11 family), WiMAX (IEEE 802.16 family), IEEE 802.20, long term evolution (LTE), Ev-DO, HSPA+, HSDPA+, HSUPA+, EDGE, GSM, GPRS, CDMA, TDMA, DECT, Bluetooth, derivatives thereof, as well as any other wireless protocols that are designated as 3G, 4G, 5G, and beyond. The computing device **800** may include a plurality of communication chips **806**. For instance, a first communication chip **806** may be dedicated to shorter range wireless communications such as Wi-Fi and Bluetooth and a second communication chip **806** may be dedicated to longer range wireless communications such as GPS, EDGE, GPRS, CDMA, WiMAX, LTE, Ev-DO, and others.

The processor **804** of the computing device **800** includes an integrated circuit die packaged within the processor **804**. In some implementations of the invention, the integrated circuit die of the processor may be packaged in an electronic system that comprises a package substrate with first dies and second dies in a face-to-face configuration, in accordance with embodiments described herein. The term “processor”

15

may refer to any device or portion of a device that processes electronic data from registers and/or memory to transform that electronic data into other electronic data that may be stored in registers and/or memory.

The communication chip **806** also includes an integrated circuit die packaged within the communication chip **806**. In accordance with another implementation of the invention, the integrated circuit die of the communication chip may be packaged in an electronic system that comprises a package substrate with first dies and second dies in a face-to-face configuration, in accordance with embodiments described herein.

The above description of illustrated implementations of the invention, including what is described in the Abstract, is not intended to be exhaustive or to limit the invention to the precise forms disclosed. While specific implementations of, and examples for, the invention are described herein for illustrative purposes, various equivalent modifications are possible within the scope of the invention, as those skilled in the relevant art will recognize.

These modifications may be made to the invention in light of the above detailed description. The terms used in the following claims should not be construed to limit the invention to the specific implementations disclosed in the specification and the claims. Rather, the scope of the invention is to be determined entirely by the following claims, which are to be construed in accordance with established doctrines of claim interpretation.

Example 1

An electronic package, comprising: a mold layer having a first surface and a second surface opposite the first surface; a plurality of first dies embedded in the mold layer, wherein each of the plurality of first dies has a surface that is substantially coplanar with the first surface of the mold layer; and a second die embedded in the mold layer, wherein the second die is positioned between the plurality of first dies and the second surface of the mold layer.

Example 2

The electronic package of Example 1, wherein the plurality of first dies are electrically coupled to the second die with first level interconnects (FLI).

Example 3

The electronic package of Example 1 or Example 2, wherein active surfaces of the plurality of first dies are oriented to be facing an active surface of the second die.

Example 4

The electronic package of Examples 1-3, wherein the plurality of first dies comprise dies fabricated at a first process node, and wherein the second die is fabricated at a second process node that is less advanced than the first process node.

Example 5

The electronic package of Examples 1-4, further comprising: a plurality of high speed input/output (HSIO) dies embedded in the mold layer.

16**Example 6**

The electronic package of Examples 1-5, wherein the plurality of HSIO dies are electrically coupled to the second die.

Example 7

The electronic package of Examples 1-6, wherein each of the plurality of HSIO dies has a surface that is substantially coplanar with the first surface of the mold layer.

Example 8

The electronic package of Examples 1-7, further comprising: a plurality of second dies.

Example 9

The electronic package of Examples 1-8, wherein the plurality of second dies are electrically coupled to each other by a bridge embedded in the mold layer.

Example 10

The electronic package of Examples 1-9, wherein the plurality of second dies is positioned between the bridge and the plurality of first dies.

Example 11

The electronic package of Examples 1-10, further comprising: mid-level interconnects (MLIs) extending from the second surface of the mold layer.

Example 12

The electronic package of Examples 1-11, wherein the MLIs are electrically coupled to the plurality of first dies and the second die by conductive pillars and pads embedded in the mold layer.

Example 13

An electronic package, comprising: a mold layer having a first surface and a second surface opposite the first surface; a plurality of first dies embedded in the mold layer; a second die embedded in the mold layer, wherein the second die is positioned between the plurality of first dies and the second surface of the mold layer; and a solder resist layer between the plurality of first dies and the second die.

Example 14

The electronic package of Example 13, wherein each of the plurality of first dies is entirely embedded in the mold layer.

Example 15

The electronic package of Example 13 or Example 14, further comprising: a plurality of high speed input/output (HSIO) dies electrically coupled to the second die.

17

Example 16

The electronic package of Examples 13-15, wherein the plurality of HSIO dies have a first thickness and the plurality of first dies have a second thickness that is different than the first thickness.

Example 17

The electronic package of Examples 13-16, wherein the plurality of first dies are fabricated at a first process node, and wherein the second die is fabricated at a second process node that is less advanced than the first process node.

Example 18

The electronic package of Examples 13-17, further comprising: a plurality of second dies, wherein each of the second dies are electrically coupled to each other by one or more bridges embedded in the mold layer.

Example 19

A method of fabricating an electronic package, comprising: placing a plurality of first dies on a carrier; disposing a first mold layer over the plurality of first dies, wherein contact pads of the first dies are exposed; attaching a second die to the plurality of first dies with first level interconnects (FLIs); and disposing a second mold layer over the second die.

Example 20

The method of Example 19, wherein the first dies are placed on the carrier with a die mounter, and wherein the second die is attached to the plurality of first dies with a thermal compression bonding (TCB) tool.

Example 21

The method of Example 19 or Example 20, further comprising: fabricating a redistribution layer above the second die; disposing a solder resist over the redistribution layer; forming openings in the solder resist; disposing mid-level interconnects (MLIs) in the openings; and removing the carrier.

Example 22

An electronic system, comprising: a board; a multi-die package coupled to the board, wherein the multi-die package comprises: a mold layer having a first surface and a second surface; a plurality of first dies, wherein the plurality of first dies are embedded in the mold layer; and a second die coupled to the plurality of first dies, wherein active surfaces of the first dies face an active surface of the second die, wherein the second die is embedded in the mold layer, and wherein the second die is between the active surface of the first dies and the second surface of the mold layer.

Example 23

The electronic system of Example 22, wherein the plurality of first dies are first process node dies, and wherein the second die is a second process node die, wherein the first process node is more advanced than the second process node.

18

Example 24

The electronic system of Example 23, further comprising: a plurality of high speed input/output (HSIO) dies embedded in the mold layer.

Example 25

The electronic system of Example 23 or Example 24, wherein the plurality of HSIO dies are electrically coupled to the second die.

What is claimed is:

1. An electronic package, comprising:

a first mold layer having a first surface and a second surface opposite the first surface;

a plurality of first dies embedded in the first mold layer, wherein each of the plurality of first dies has a surface that is substantially coplanar with the first surface of the first mold layer;

a second die embedded in a second mold layer, wherein the second die is positioned vertically over the plurality of first dies, wherein the second mold layer is not vertically between the second die and the plurality of first dies;

a first plurality of vias in the second mold layer, the first plurality of vias laterally spaced apart from a first side of the second die, wherein the first plurality of vias extend along an entire vertical length of the second die; and

a second plurality of vias in the second mold layer, the second plurality of vias laterally spaced apart from a second side of the second die, the second side opposite the first side, wherein the second plurality of vias extend along an entire vertical length of the second die.

2. The electronic package of claim **1**, wherein the plurality of first dies are electrically coupled to the second die with first level interconnects (FLI).

3. The electronic package of claim **2**, wherein active surfaces of the plurality of first dies are oriented to be facing an active surface of the second die.

4. The electronic package of claim **1**, wherein the plurality of first dies comprise dies fabricated at a first process node, and wherein the second die is fabricated at a second process node that is less advanced than the first process node.

5. The electronic package of claim **1**, further comprising: a plurality of high speed input/output (HSIO) dies embedded in the first mold layer.

6. The electronic package of claim **5**, wherein the plurality of HSIO dies are electrically coupled to the second die.

7. The electronic package of claim **5**, wherein each of the plurality of HSIO dies has a surface that is substantially coplanar with the first surface of the first mold layer.

8. The electronic package of claim **1**, further comprising: a plurality of second dies.

9. The electronic package of claim **8**, wherein the plurality of second dies are electrically coupled to each other by a bridge embedded in a third mold layer.

10. The electronic package of claim **9**, wherein the plurality of second dies is positioned between the bridge and the plurality of first dies.

11. The electronic package of claim **1**, further comprising: mid-level interconnects (MLIs).

12. The electronic package of claim **11**, wherein the MLIs are electrically coupled to the plurality of first dies and the second die by conductive pillars and pads.

19

13. An electronic package, comprising:
 a first mold layer having a first surface and a second surface opposite the first surface;
 a plurality of first dies embedded in the first mold layer;
 a second die embedded in a second mold layer, wherein the second die is positioned vertically over the plurality of first dies, wherein the first mold layer is not vertically between the second die and the plurality of first dies;
 a solder resist layer between the plurality of first dies and the second die;
 a first plurality of vias in the second mold layer, the first plurality of vias laterally spaced apart from a first side of the second die; and
 a second plurality of vias in the second mold layer, the second plurality of vias laterally spaced apart from a second side of the second die, the second side opposite the first side.

14. The electronic package of claim 13, wherein each of the plurality of first dies is entirely embedded in the first mold layer.

15. The electronic package of claim 13, further comprising:
 a plurality of high speed input/out (HSIO) dies electrically coupled to the second die.

16. The electronic package of claim 15, wherein the plurality of HSIO dies have a first thickness and the plurality of first dies have a second thickness that is different than the first thickness.

17. The electronic package of claim 13, wherein the plurality of first dies are fabricated at a first process node, and wherein the second die is fabricated at a second process node that is less advanced than the first process node.

18. The electronic package of claim 13, further comprising:
 a plurality of second dies, wherein each of the second dies are electrically coupled to each other by one or more bridges embedded in a third mold layer.

19. A method of fabricating an electronic package, comprising:
 placing a plurality of first dies on a carrier;
 disposing a first mold layer over the plurality of first dies, wherein contact pads of the first dies are exposed;
 attaching a second die to the plurality of first dies with first level interconnects (FLIs);
 disposing a second mold layer over the second die, wherein the second mold layer is not vertically between the second die and the plurality of first dies;
 forming a first plurality of vias in the second mold layer, the first plurality of vias laterally spaced apart from a first side of the second die, wherein the first plurality of vias extend along an entire vertical length of the second die; and
 forming a second plurality of vias in the second mold layer, the second plurality of vias laterally spaced apart from a second side of the second die, the second side

20

opposite the first side, wherein the second plurality of vias extend along an entire vertical length of the second die.

20. The method of claim 19, wherein the first dies are placed on the carrier with a die mouter, and wherein the second die is attached to the plurality of first dies with a thermal compression bonding (TCB) tool.

21. The method of claim 19, further comprising:
 fabricating a redistribution layer above the second die;
 disposing a solder resist over the redistribution layer;
 forming openings in the solder resist;
 disposing mid-level interconnects (MLIs) in the openings;
 and
 removing the carrier.

22. An electronic system, comprising:
 a board;
 a multi-die package coupled to the board, wherein the multi-die package comprises:
 a first mold layer having a first surface and a second surface;
 a plurality of first dies, wherein the plurality of first dies are embedded in the first mold layer; and
 a second die coupled to the plurality of first dies, wherein active surfaces of the first dies face an active surface of the second die, wherein the second die is embedded in a second mold layer, wherein the second die is vertically over the active surface of the first dies, and wherein the second mold layer is not vertically between the second die and the plurality of first dies;
 a first plurality of vias in the second mold layer, the first plurality of vias laterally spaced apart from a first side of the second die, wherein the first plurality of vias extend along an entire vertical length of the second die; and
 a second plurality of vias in the second mold layer, the second plurality of vias laterally spaced apart from a second side of the second die, the second side opposite the first side, wherein the second plurality of vias extend along an entire vertical length of the second die.

23. The electronic system of claim 22, wherein the plurality of first dies are first process node dies, and wherein the second die is a second process node die, wherein the first process node is more advanced than the second process node.

24. The electronic system of claim 22, further comprising:
 a plurality of high speed input/out (HSIO) dies embedded in the first mold layer.

25. The electronic system of claim 24, wherein the plurality of HSIO dies are electrically coupled to the second die.

* * * * *